



# MPQ4436A

## 45V, 6A, Low- $I_Q$ , Fixed-Output, Synchronous Step-Down Converter, AEC-Q100 Qualified

### DESCRIPTION

The MPQ4436A is a configurable-frequency, synchronous, step-down switching regulator with integrated internal high-side and low-side power MOSFETs (HS-FET and LS-FET, respectively). It provides up to 6A of highly efficient output current ( $I_{OUT}$ ), with current mode control for fast loop response.

The wide 3.3V to 45V input voltage ( $V_{IN}$ ) range accommodates a variety of step-down applications in automotive input environments. A 1.7 $\mu$ A shutdown mode quiescent current ( $I_Q$ ) allows the part to be used in battery-powered applications.

High power conversion efficiency across a wide load range is achieved by scaling down the switching frequency ( $f_{SW}$ ) under light-load conditions to reduce the switching and gate driver losses.

An open-drain power good (PG) signal indicates whether the output is within 95% to 105% of its nominal voltage.

Frequency foldback helps prevent inductor current runaway during start-up. Thermal shutdown provides reliable, fault-tolerant operation. High duty cycle and low-dropout mode are provided for automotive cold-crank conditions.

The MPQ4436A is available in a QFN-20 (4mmx4mm) package.

### FEATURES

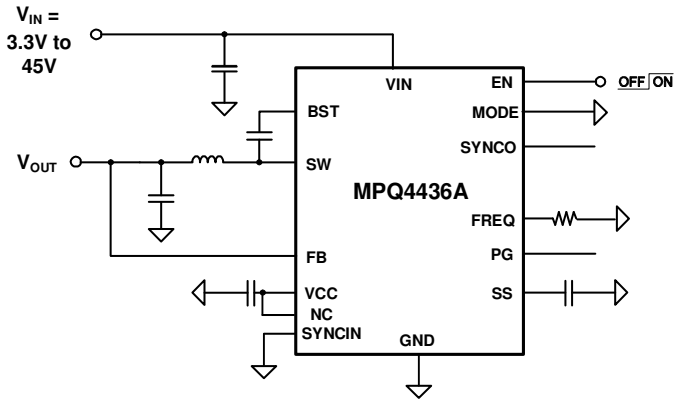
- Wide 3.3V to 45V Operating Input Voltage ( $V_{IN}$ ) Range
- 6A Continuous Output Current ( $I_{OUT}$ )
- 1.7 $\mu$ A Low Shutdown Supply Current
- 18 $\mu$ A Sleep Mode Quiescent Current ( $I_Q$ )
- Internal 48m $\Omega$  High-Side MOSFET (HS-FET) and 20m $\Omega$  Low-Side MOSFET (LS-FET)
- 350kHz to 1000kHz Configurable Switching Frequency ( $f_{SW}$ ) for  $V_{OUT} < 5V$  Car Battery Applications
- Synchronizable to an External Clock
- Out-of-Phase Synchronized Clock Output
- Fixed Output Version: 3.3V, 5V
- Frequency Spread Spectrum (FSS) for Low EMI
- Symmetric  $V_{IN}$  for Low EMI
- Power Good (PG) Output
- External Soft Start (SS)
- 100ns Minimum On Time
- Selectable Advanced Asynchronous Modulation (AAM) Mode or Forced Continuous Conduction Mode (FCCM)
- Low-Dropout Mode
- Hiccup Over-Current Protection (OCP)
- Available in a QFN-20 (4mmx4mm) Package
- Available in a Wettable Flank Package
- Available in AEC-Q100 Grade 1

### APPLICATIONS

- Automotive Infotainment
- Automotive Clusters
- Advanced Driver Assistance Systems (ADAS)
- Industrial Power Systems

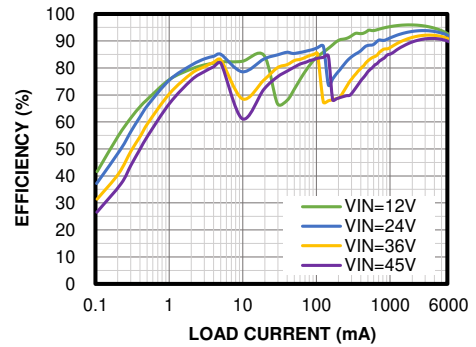
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## TYPICAL APPLICATION



### Efficiency vs. Load Current

$V_{OUT} = 5V$ ,  $f_{sw} = 470kHz$ ,  $L = 4.7\mu H$   
(DCR = 15m $\Omega$ ), AAM mode



### ORDERING INFORMATION

Part Number*	Package	Top Marking	MSL Rating**
MPQ4436AGRE-33-AEC1***	QFN-20 (4mmx4mm)	See Below	1
MPQ4436AGRE-5-AEC1***	QFN-20 (4mmx4mm)	See Below	1

\* For Tape & Reel, add suffix -Z (e.g. MPQ4436GRE-33-AEC1-Z).

\*\*Moisture Sensitivity Level Rating

\*\*\*Wettable flank

### TOP MARKING

**MPSYWW**

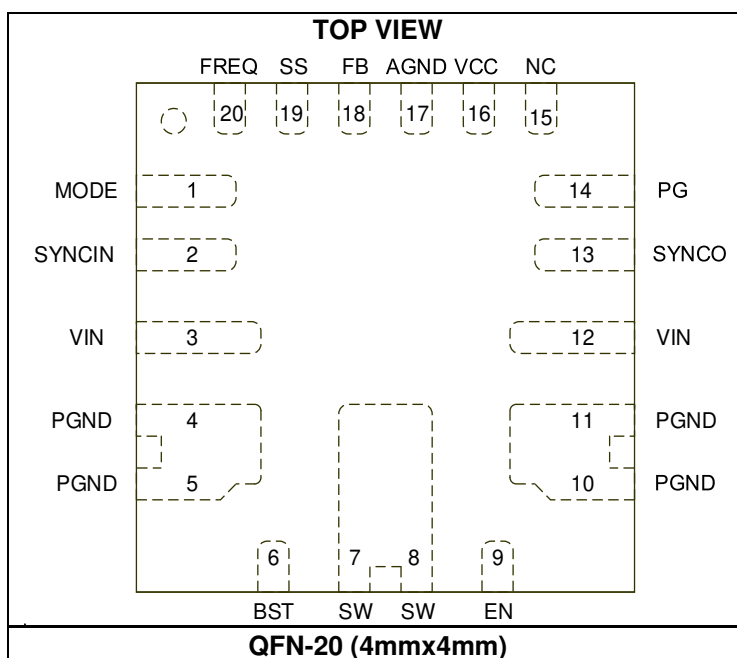
**MP4436**

**LLLLLL**

**E**

MPS: MPS prefix  
 Y: Year code  
 WW: Week code  
 MP4436: Part number  
 LLLLLL: Lot number  
 E: Wettable flank

### PACKAGE REFERENCE



## PIN FUNCTIONS

Pin #	Name	Description
1	MODE	<b>AAM or FCCM selection pin.</b> Pull this pin high to put the part in forced continuous conduction mode (FCCM). Pull it low to make the part operate in advanced asynchronous modulation (AAM) mode under light loads. Do not leave this pin floating.
2	SYNCIN	<b>SYNC input.</b> Connect a 51k $\Omega$ resistor between SYNCIN and GND. Apply a 350kHz to 1000kHz clock signal to this pin to synchronize the internal oscillator frequency to the external clock. Connect this pin to GND if not used; do not float this pin.
3, 12	VIN	<b>Input supply.</b> VIN supplies power to all of the internal control circuitry and the power MOSFET connected to SW. It is recommended to place a decoupling capacitor to ground close to VIN to minimize switching spikes.
4, 5, 10, 11	PGND	<b>Power ground.</b>
6	BST	<b>Bootstrap.</b> BST is the positive power supply for the high-side MOSFET (HS-FET) driver connected to SW. Connect a bypass capacitor between BST and SW. See the Application Information section on page 32 to calculate the size of this capacitor.
7, 8	SW	<b>Switch node.</b> SW is the output of the internal power MOSFET.
9	EN	<b>Enable.</b> Pull this pin below 0.85V to shut down the chip. Pull it above 1V to enable the chip.
13	SYNCO	<b>SYNC output.</b> This pin outputs a clock signal that is 180° out of phase with the internal oscillator signal, or 180° out of phase with the clock signal applied at SYNCIN pin. Leave this pin floating if not used.
14	PG	<b>Power good (PG) indicator.</b> PG's output is an open drain. A pull-up resistor connected to the power source is required if PG is used. If the output voltage ( $V_{OUT}$ ) is within 95% to 105% of the nominal voltage, this pin goes high. If $V_{OUT}$ is above 106.5% or below 93.5% of the nominal voltage, this pin goes low.
15	NC	<b>Not connected.</b> Connect this pin to the VCC pin or $V_{OUT}$ , which must be no less than 3V. Do not float this pin.
16	VCC	<b>Bias supply.</b> This supplies power to the internal control circuit and gate drivers. A decoupling capacitor to ground is required close to this pin. See the Application Information section on page 32 to calculate the size of this capacitor.
17	AGND	<b>Analog ground.</b>
18	FB	<b>Feedback input.</b> Connect the FB pin directly to the output. Avoid placing vias on the FB traces.
19	SS	<b>Soft start (SS) input.</b> Place a capacitor from SS to GND to set the soft-start time ( $t_{SS}$ ). The MPQ4436A sources 6 $\mu$ A from SS to the soft-start capacitor ( $C_{SS}$ ) at start-up. As the SS voltage ( $V_{SS}$ ) rises, the feedback threshold voltage increases to limit inrush current during start-up.
20	FREQ	<b>Switching frequency setting.</b> Connect a resistor from this pin to GND to set the switching frequency ( $f_{SW}$ ). See the $f_{SW}$ vs. $R_{FREQ}$ curve in the Typical Performance Characteristics section on page 15 to set the frequency.

**ABSOLUTE MAXIMUM RATINGS** <sup>(1)</sup>

V <sub>IN</sub> , EN.....	-0.3V to +50V
SW .....	-0.3V to V <sub>IN (MAX)</sub> + 0.3V
BST .....	V <sub>SW</sub> + 5.5V
All other pins.....	-0.3V to +5.5V
Continuous power dissipation (T <sub>A</sub> = 25°C) <sup>(2) (4)</sup>	
QFN-20 (4mmx4mm) .....	2.84W
Operating junction temperature.....	150°C
Lead temperature .....	260°C
Storage temperature.....	-65°C to +150°C

**ESD Ratings**

Human body model (HBM) .....	±2kV
Charged device model (CDM) .....	±750V

**Recommended Operating Conditions**

Supply voltage (V <sub>IN</sub> ) .....	3.3V to 45V
Operating junction temp (T <sub>J</sub> ) ....	-40°C to +150°C

**Thermal Resistance**
**θ<sub>JA</sub>    θ<sub>JC</sub>**

QFN-20 (4mmx4mm)		
JESD51-7 <sup>(3)</sup> .....	44.....	9....°C/W
EVB4436A-R-00A <sup>(4)</sup> .....	23.....	2.5..°C/W

**Notes:**

- 1) Exceeding these ratings may damage the device.
- 2) The maximum allowable power dissipation is a function of the maximum junction temperature T<sub>J</sub> (MAX), the junction-to-ambient thermal resistance θ<sub>JA</sub>, and the ambient temperature T<sub>A</sub>. The maximum allowable continuous power dissipation at any ambient temperature is calculated by P<sub>D</sub> (MAX) = (T<sub>J</sub> (MAX) - T<sub>A</sub>) / θ<sub>JA</sub>. Exceeding the maximum allowable power dissipation can cause excessive die temperature, and the regulator may go into thermal shutdown. Internal thermal shutdown circuitry protects the device from permanent damage.
- 3) Measured on JESD51-7, 4-layer PCB. The values given in this table are only valid for comparison with other packages and cannot be used for design purposes. These values were calculated in accordance with JESD51-7, and simulated on a specified JEDEC board. They do not represent the performance obtained in an actual application.
- 4) Measured on an MPS standard EVB: 9cmx9cm, 2oz copper thickness, 4-layer PCB.

## ELECTRICAL CHARACTERISTICS

$V_{IN} = 12V$ ,  $V_{EN} = 2V$ ,  $T_J = -40^{\circ}C$  to  $+125^{\circ}C$ , typical values are at  $T_J = 25^{\circ}C$ , unless otherwise noted.

Parameter	Symbol	Condition	Min	Typ	Max	Units
$V_{IN}$ under-voltage lockout (UVLO) rising threshold	$V_{IN\_UVLO\_RISING}$		2.8	3	3.2	V
$V_{IN}$ UVLO falling threshold	$V_{IN\_UVLO\_FALLING}$		2.5	2.7	2.9	V
$V_{IN}$ UVLO hysteresis	$V_{IN\_UVLO\_HYS}$			280		mV
VCC voltage	$V_{CC}$	$I_{VCC} = 0A$	4.6	4.9	5.2	V
VCC regulation		$I_{VCC} = 30mA$		1	4	%
VCC current limit	$I_{LIMIT\_VCC}$	$V_{CC} = 4V$	100			mA
$V_{IN}$ quiescent current	$I_Q$	FB high, no load, (sleep mode)		18	26	$\mu A$
$V_{IN}$ quiescent current (switching) (5)	$I_{Q\_ACTIVE}$	MODE = GND (AAM), switching, no load,		20		$\mu A$
		MODE = high (FCCM), switching, $f_{sw} = 2MHz$ , no load		40		mA
		MODE = high (FCCM), switching, $f_{sw} = 470kHz$ , no load		9.5		mA
$V_{IN}$ shutdown current	$I_{SHDN}$	$EN = 0V$		1.7	2.5	$\mu A$
Output voltage accuracy of the MPQ4436A-33	$V_{OUT}$	$T_J = 25^{\circ}C$	3234	3300	3366	mV
			3201	3300	3399	
Output voltage accuracy of the MPQ4436A-5	$V_{OUT}$	$T_J = 25^{\circ}C$	4900	5000	5100	mV
			4850	5000	5150	
Switching frequency	$f_{sw}$	$R_{FREQ} = 62k\Omega$	420	470	520	kHz
		$R_{FREQ} = 26.1k\Omega$	820	1000	1180	
Minimum on time (5)	$t_{ON\_MIN}$			100		ns
Minimum off time (5)	$t_{OFF\_MIN}$			80		ns
SYNCIN voltage rising threshold	$V_{SYNC\_RISING}$		1.8			V
SYNCIN voltage falling threshold	$V_{SYNC\_FALLING}$				0.4	V
SYNCIN clock range	$f_{SYNC}$	External clock	350		1000	kHz
SYNCO high voltage	$V_{SYNCO\_HIGH}$	$I_{SYNCO} = -1mA$	3.3	4.5		V
SYNCO low voltage	$V_{SYNCO\_LOW}$	$I_{SYNCO} = 1mA$			0.4	V
SYNCO phase shift		Tested under SYNCIN		180		deg
High-side (HS) current limit	$I_{LIMIT}$	Duty cycle = 30%	10	13	16	A
Low-side (LS) valley current limit	$I_{LIMIT\_VALLEY}$		8	10	12	A
ZCD current	$I_{ZCD}$	AAM mode	-0.15	0.1	0.35	A
LS reverse current limit	$I_{LIMIT\_REVERSE}$	FCCM	2	4.5	6.5	A
Switch leakage current	$I_{SW\_LKG}$			0.01	1	$\mu A$
High-side MOSFET (HS-FET) on resistance	$R_{DS(ON)\_HS}$	$V_{BST} - V_{SW} = 5V$		48	80	m $\Omega$
Low-side MOSFET (LS-FET) on resistance	$R_{DS(ON)\_LS}$	$V_{CC} = 5V$		20	40	m $\Omega$
Soft-start current	$I_{SS}$	$V_{SS} = 0V$	4	6	8	$\mu A$

**ELECTRICAL CHARACTERISTICS (continued)**
**V<sub>IN</sub> = 12V, V<sub>EN</sub> = 2V, T<sub>J</sub> = -40°C to +125°C, typical values are at T<sub>J</sub> = 25°C, unless otherwise noted.**

Parameter	Symbol	Condition	Min	Typ	Max	Units
EN rising threshold	V <sub>EN_RISING</sub>		0.8	1	1.2	V
EN falling threshold	V <sub>EN_FALLING</sub>		0.65	0.85	1.05	V
EN hysteresis voltage	V <sub>EN_HYS</sub>			180		mV
MODE rising threshold	V <sub>MODE_RISING</sub>		1.8			V
MODE falling threshold	V <sub>MODE_FALLING</sub>				0.4	V
PG rising threshold (V <sub>FB</sub> / V <sub>OUT</sub> )	P <sub>G</sub> RISING	V <sub>FB</sub> rising	92%	95%	98%	V <sub>OUT</sub>
		V <sub>FB</sub> falling	102%	105%	108%	
PG falling threshold (V <sub>FB</sub> / V <sub>OUT</sub> )	P <sub>G</sub> FALLING	V <sub>FB</sub> falling	90.5%	93.5%	96.5%	
		V <sub>FB</sub> rising	103.5%	106.5%	109.5%	
PG output voltage low	V <sub>PG_LOW</sub>	I <sub>SINK</sub> = 1mA		0.1	0.3	V
PG rising delay	t <sub>PG_R_DELAY</sub>			35		μs
PG falling delay	t <sub>PG_F_DELAY</sub>			35		μs
Thermal shutdown <sup>(5)</sup>	t <sub>SD</sub>			170		°C
Thermal shutdown hysteresis <sup>(5)</sup>	t <sub>SD_HYS</sub>			20		°C

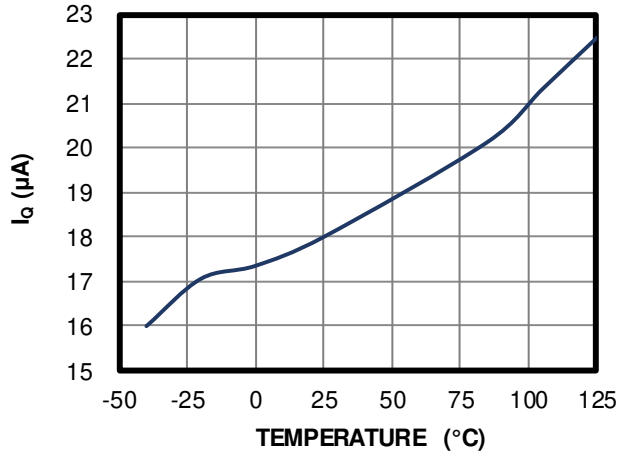
**Note:**

5) Derived from bench characterization, not tested in production.

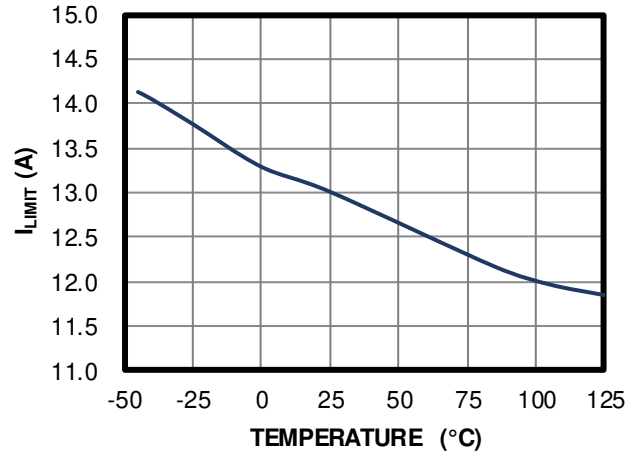
## TYPICAL CHARACTERISTICS

$V_{IN} = 12V$ ,  $T_J = -40^{\circ}C$  to  $+125^{\circ}C$ , unless otherwise noted.

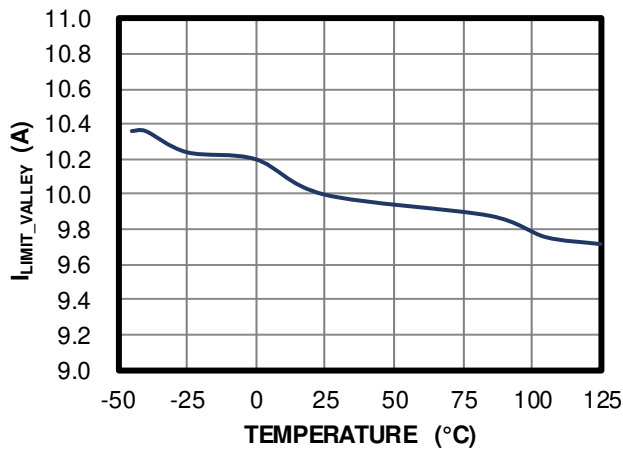
$I_Q$  vs. Temperature



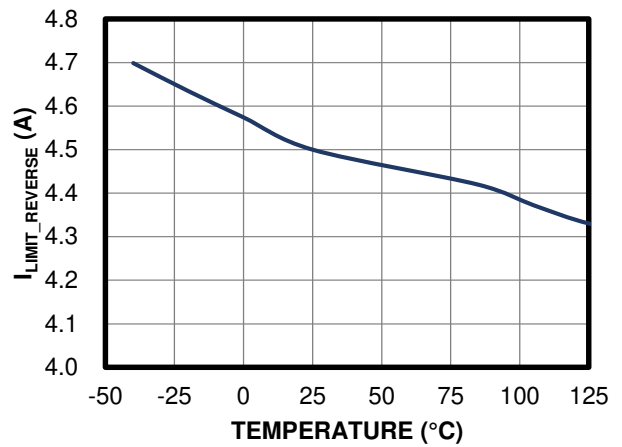
$I_{LIMIT}$  vs. Temperature



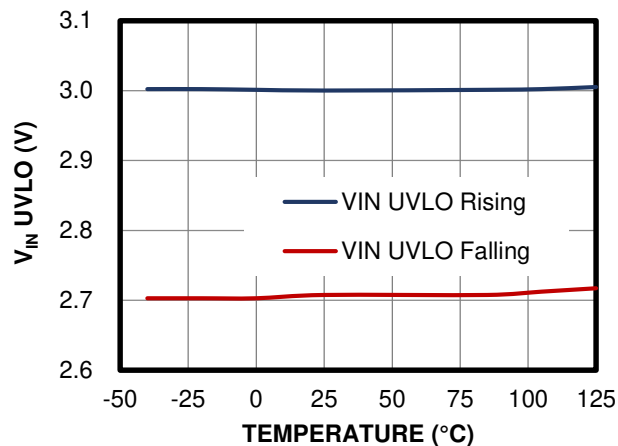
Valley Current Limit vs. Temperature



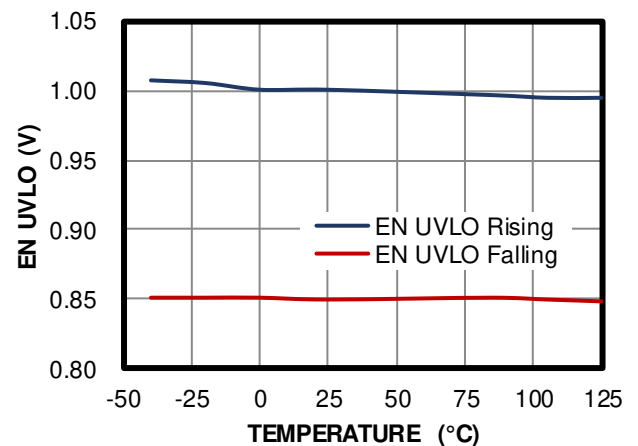
Reverse Current Limit vs. Temperature



$V_{IN}$  UVLO Threshold vs. Temperature

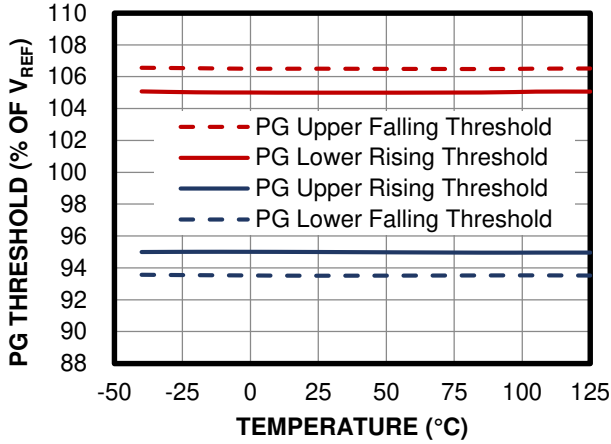
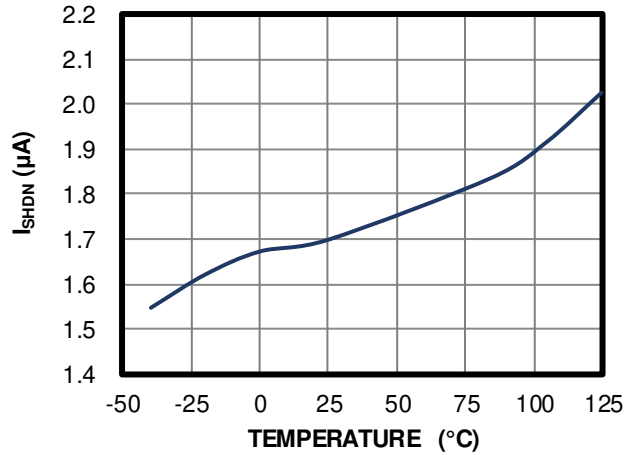
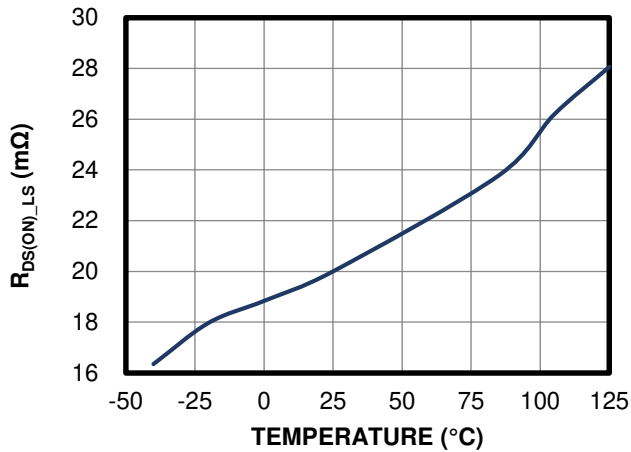
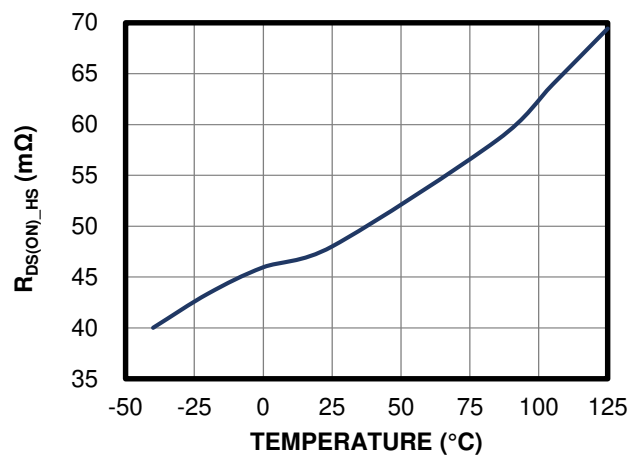
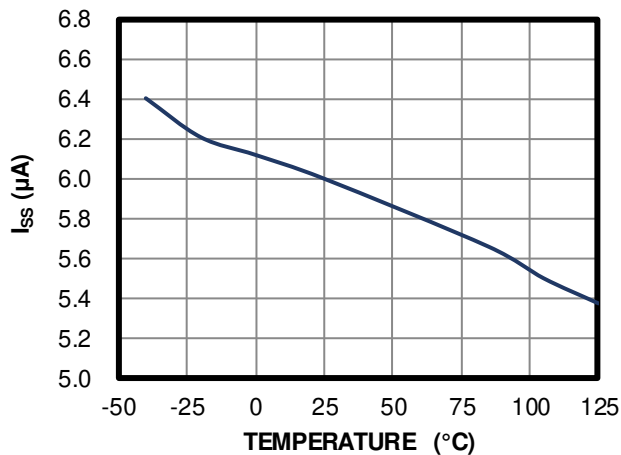
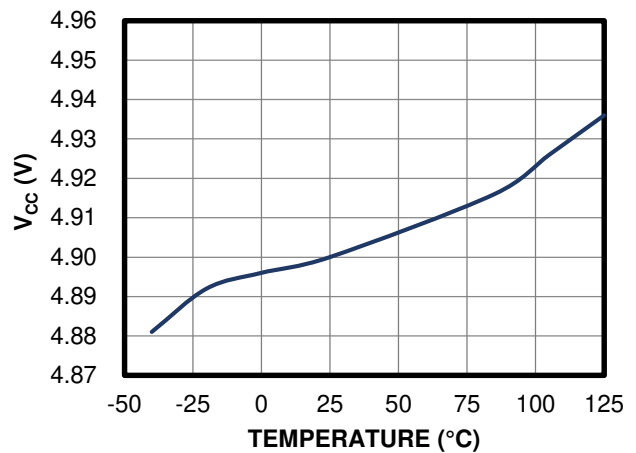


EN UVLO Threshold vs. Temperature

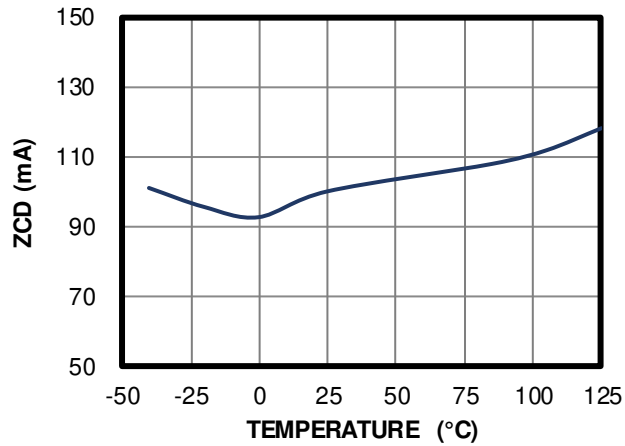
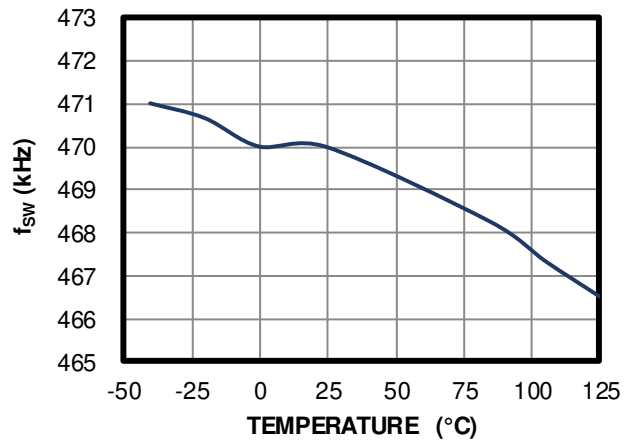




**TYPICAL CHARACTERISTICS (continued)**
 $V_{IN} = 12V$ ,  $T_J = -40^{\circ}C$  to  $+125^{\circ}C$ , unless otherwise noted.

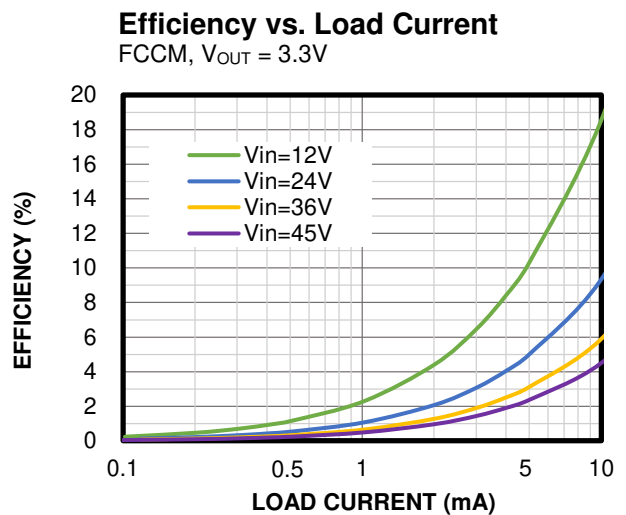
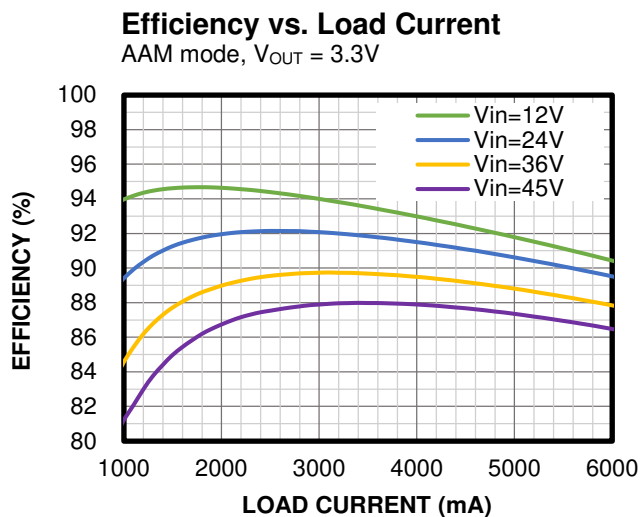
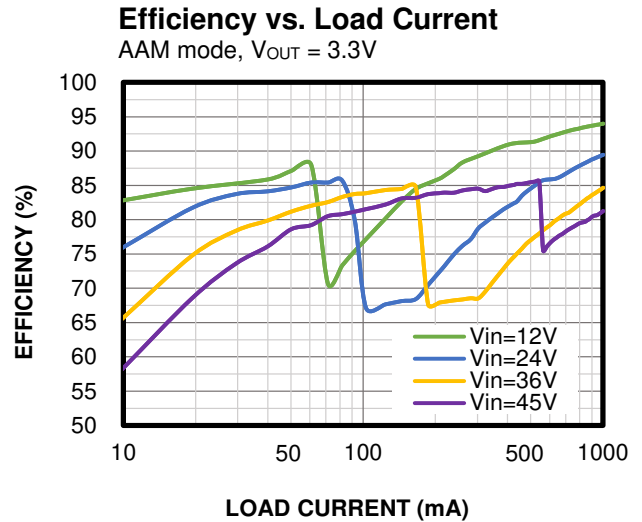
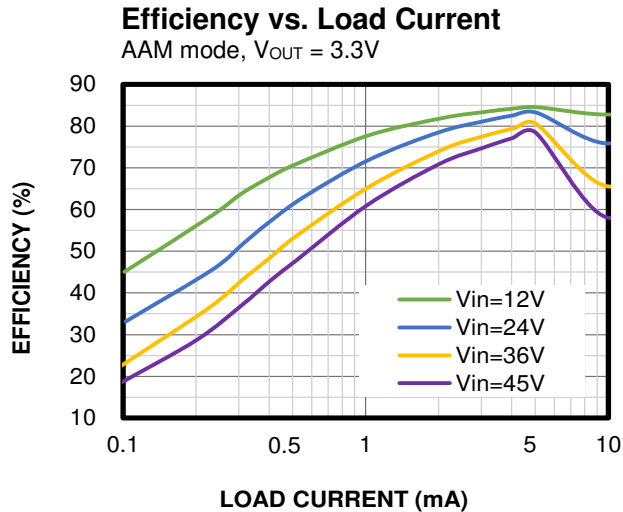
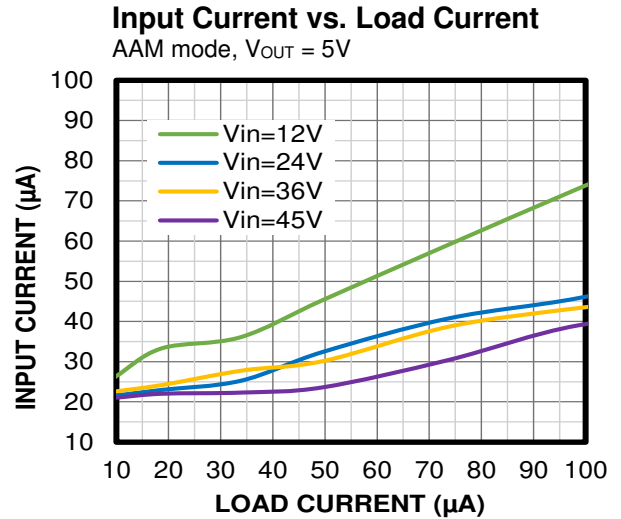
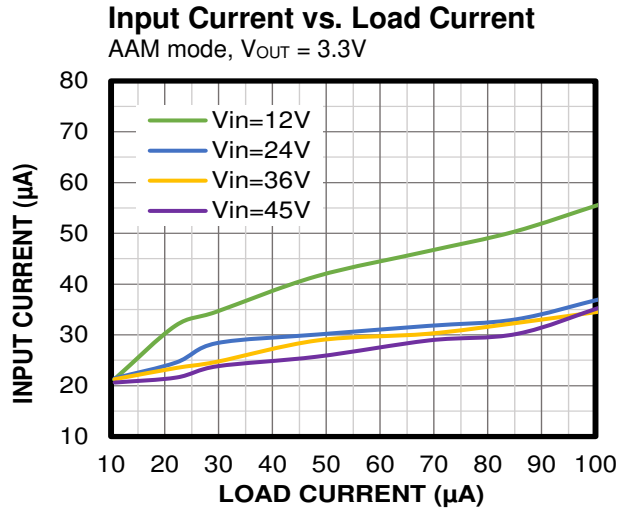
**PG Rising/Falling Threshold vs. Temperature**

 **$V_{IN}$  Shutdown Current vs. Temperature**

 **$R_{DS(ON)_LS}$  vs. Temperature**

 **$R_{DS(ON)_HS}$  vs. Temperature**

**Soft-Start Current vs. Temperature**

 **$V_{CC}$  vs. Temperature**


**TYPICAL CHARACTERISTICS (continued)**
 $V_{IN} = 12V$ ,  $T_J = -40^{\circ}C$  to  $+125^{\circ}C$ , unless otherwise noted.

**ZCD vs. Temperature**

 **$f_{SW}$  vs. Temperature**
 $R_{FREQ} = 62k\Omega$ 


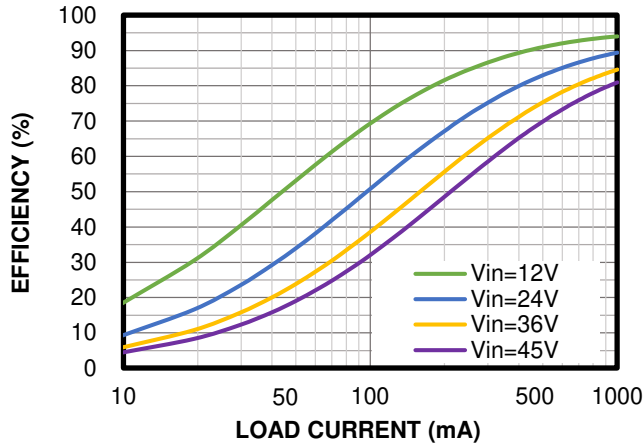
## TYPICAL PERFORMANCE CHARACTERISTICS

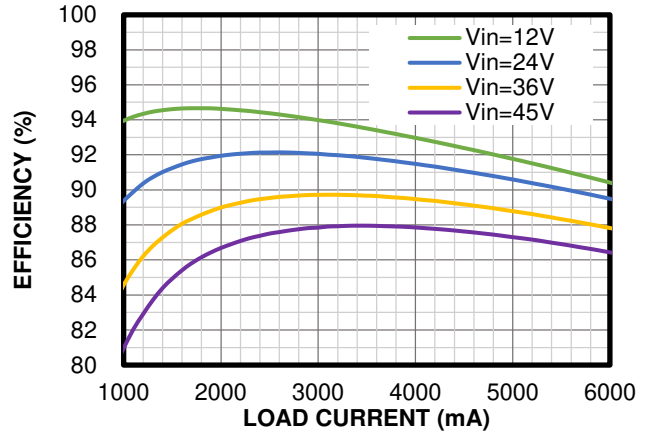
$V_{IN} = 12V$ ,  $V_{OUT} = 3.3V$ ,  $L = 4.7\mu H$  <sup>(6)</sup>,  $f_{SW} = 470kHz$ , AAM mode,  $T_A = 25^\circ C$ , unless otherwise noted.

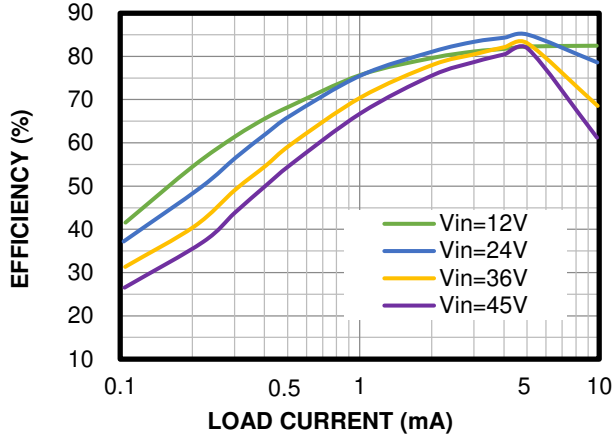


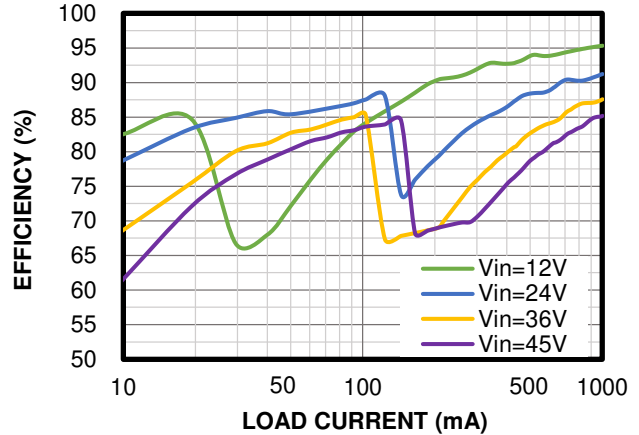
**TYPICAL PERFORMANCE CHARACTERISTICS (continued)**
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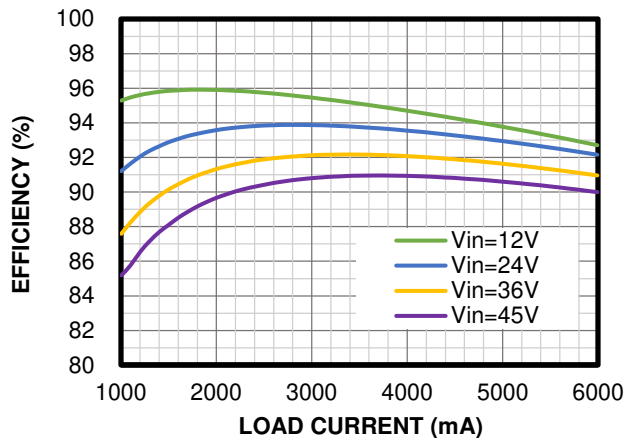
**Efficiency vs. Load Current**

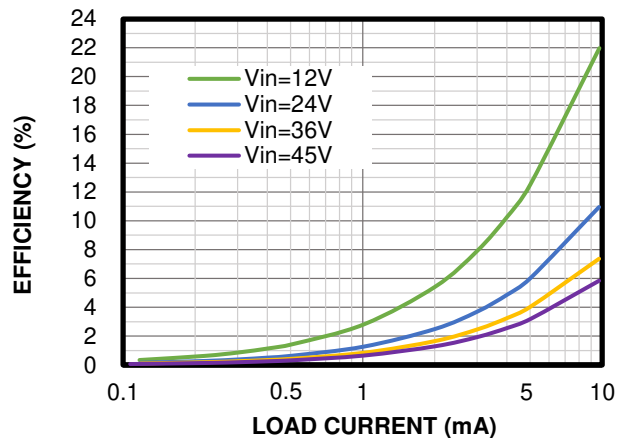
 FCCM,  $V_{OUT} = 3.3V$ 

**Efficiency vs. Load Current**

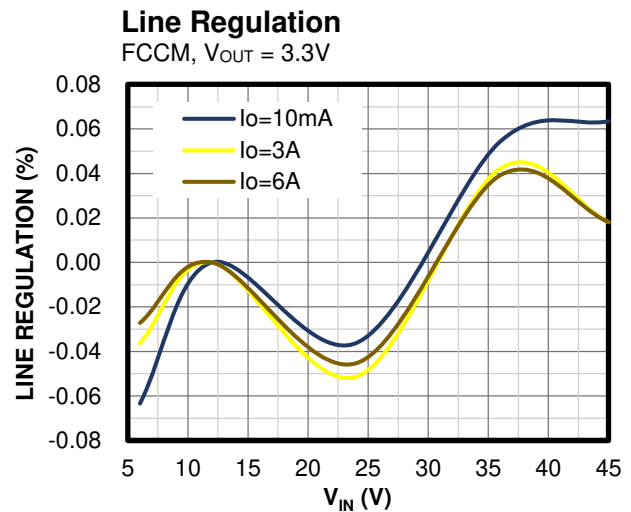
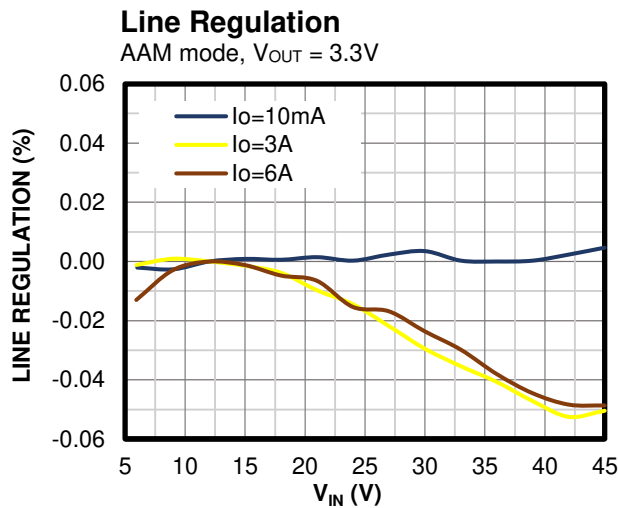
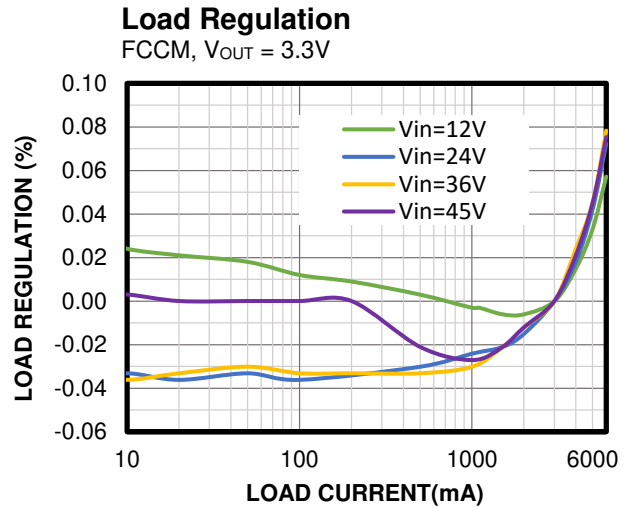
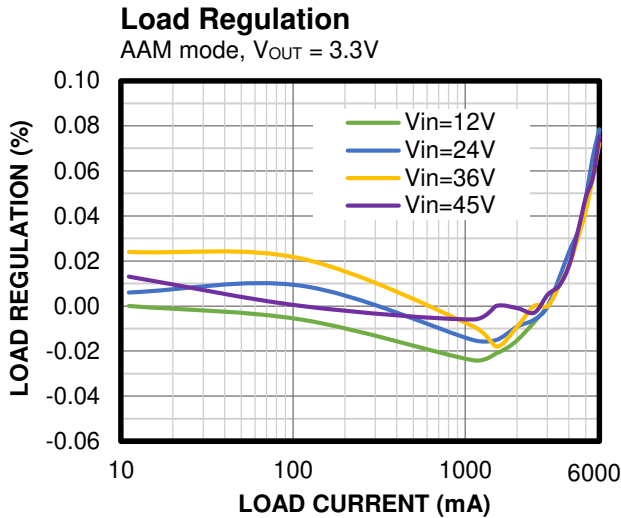
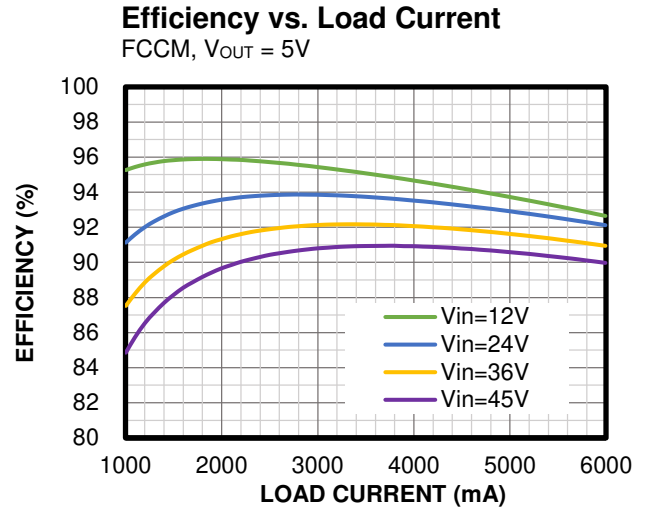
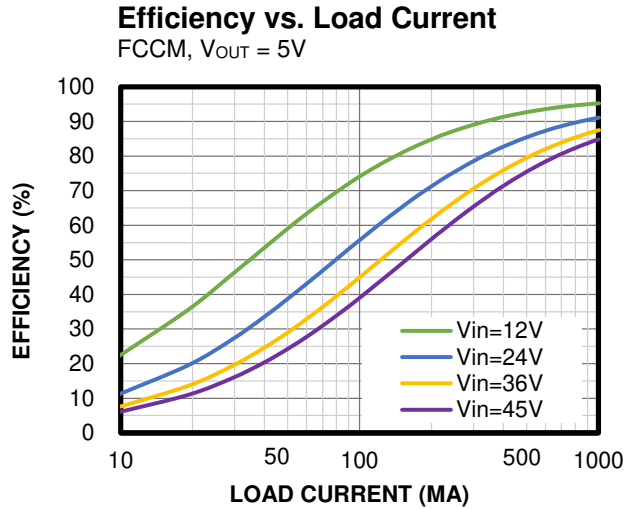
 FCCM,  $V_{OUT} = 3.3V$ 

**Efficiency vs. Load Current**

 AAM mode,  $V_{OUT} = 5V$ 

**Efficiency vs. Load Current**

 AAM mode,  $V_{OUT} = 5V$ 

**Efficiency vs. Load Current**

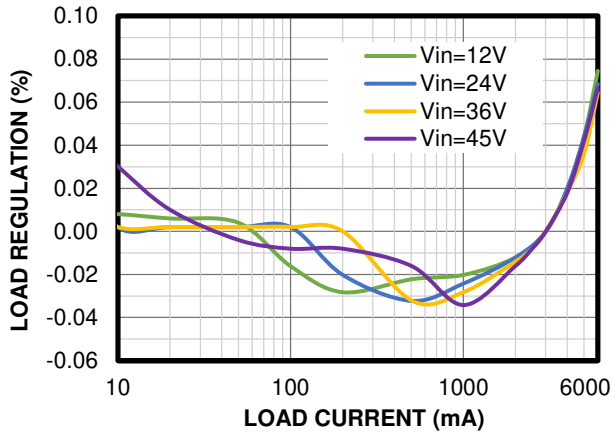
 AAM mode,  $V_{OUT} = 5V$ 

**Efficiency vs. Load Current**

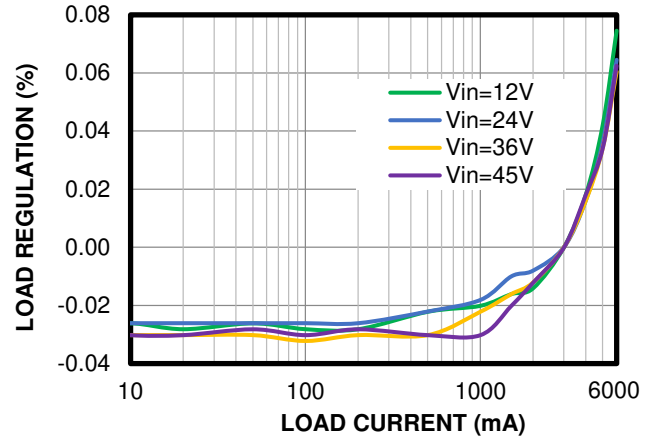
 FCCM,  $V_{OUT} = 5V$ 


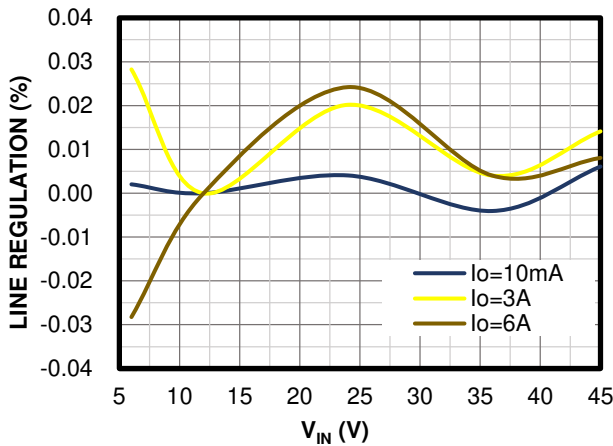
**TYPICAL PERFORMANCE CHARACTERISTICS (continued)**
 $V_{IN} = 12V$ ,  $V_{OUT} = 3.3V$ ,  $L = 4.7\mu H$  <sup>(6)</sup>,  $f_{SW} = 470kHz$ , AAM mode,  $T_A = 25^\circ C$ , unless otherwise noted.


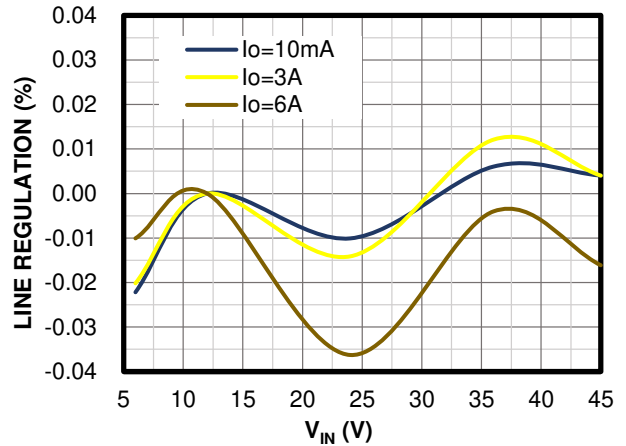
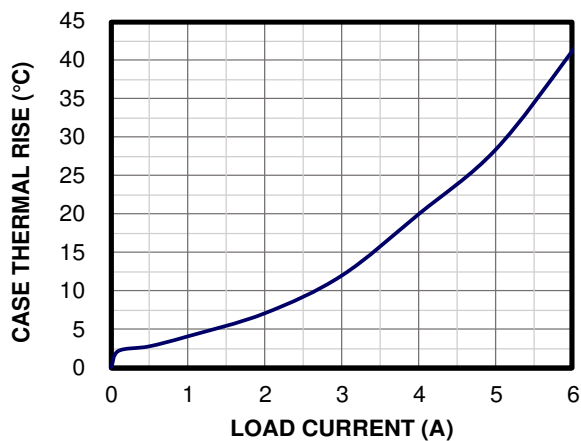
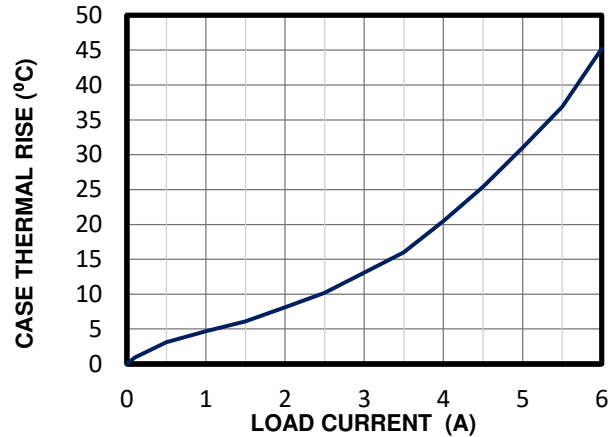
**TYPICAL PERFORMANCE CHARACTERISTICS (continued)**
 $V_{IN} = 12V$ ,  $V_{OUT} = 3.3V$ ,  $L = 4.7\mu H$  <sup>(6)</sup>,  $f_{SW} = 470kHz$ , AAM mode,  $T_A = 25^\circ C$ , unless otherwise noted.

**Load Regulation**

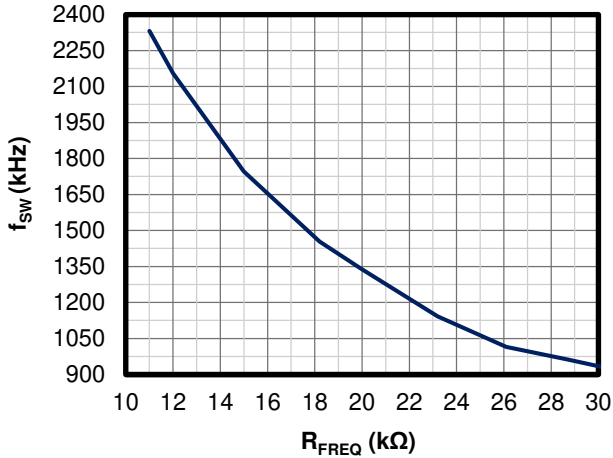
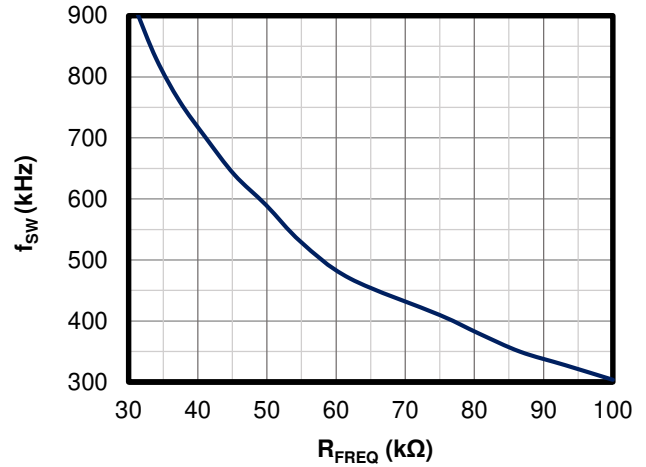
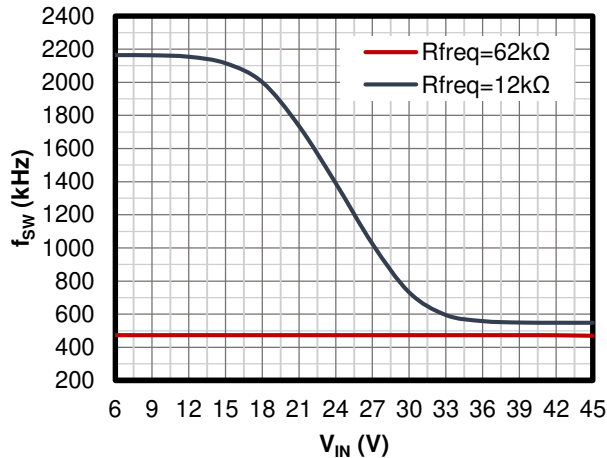
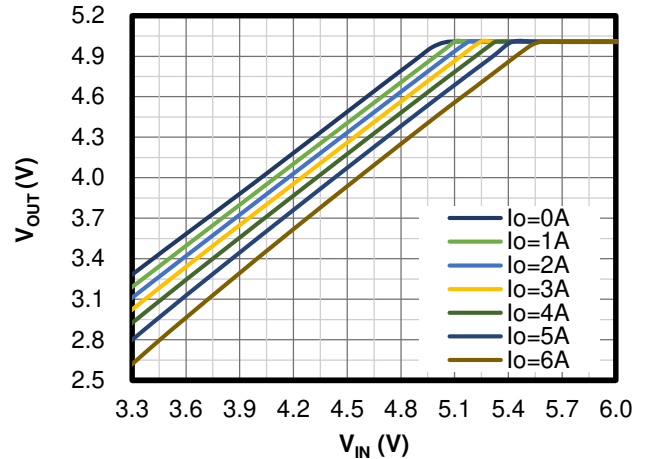
 AAM mode,  $V_{OUT} = 5V$ 

**Load Regulation**

 FCCM,  $V_{OUT} = 5V$ 

**Line Regulation**

 AAM mode,  $V_{OUT} = 5V$ 

**Line Regulation**

 FCCM,  $V_{OUT} = 5V$ 

**Case Thermal Rise**
 $V_{OUT} = 3.3V$ 

**Case Thermal Rise**
 $V_{OUT} = 5V$ 


**TYPICAL PERFORMANCE CHARACTERISTICS (continued)**
 $V_{IN} = 12V$ ,  $V_{OUT} = 3.3V$ ,  $L = 4.7\mu H$  <sup>(6)</sup>,  $f_{SW} = 470kHz$ , AAM mode,  $T_A = 25^\circ C$ , unless otherwise noted.

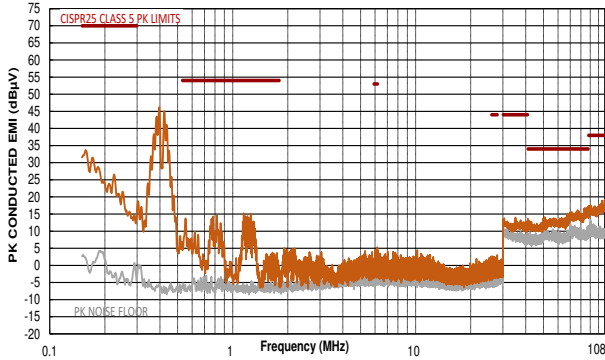
 **$f_{SW}$  vs.  $R_{FREQ}$**   
 $R_{FREQ} = 10k\Omega$  to  $30k\Omega$ 

 **$f_{SW}$  vs.  $R_{FREQ}$**   
 $R_{FREQ} = 30k\Omega$  to  $100k\Omega$ 

 **$f_{SW}$  vs.  $V_{IN}$** 

**Low-Dropout Mode**
 $V_{OUT} = 5V$ 


## TYPICAL PERFORMANCE CHARACTERISTICS *(continued)*

$V_{IN} = 12V$ ,  $V_{OUT} = 5V$ ,  $I_{OUT} = 6A$ ,  $L = 4.7\mu H$  <sup>(6)</sup>,  $f_{SW} = 410kHz$ ,  $T_A = 25^\circ C$ , unless otherwise noted.<sup>(7)</sup>

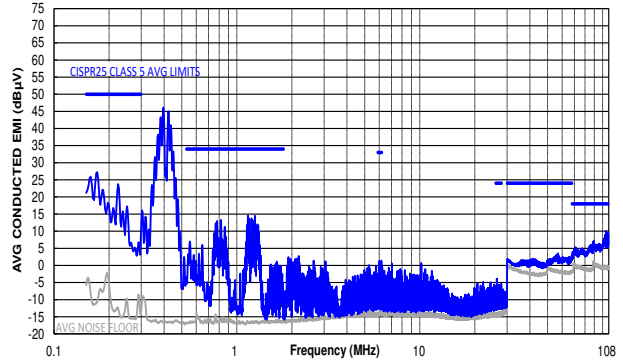
### CISPR25 Class 5 Peak Conducted Emissions

150kHz to 108MHz



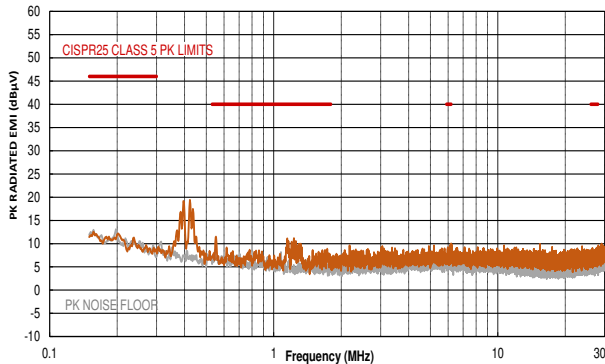
### CISPR25 Class 5 Average Conducted Emissions

150kHz to 108MHz



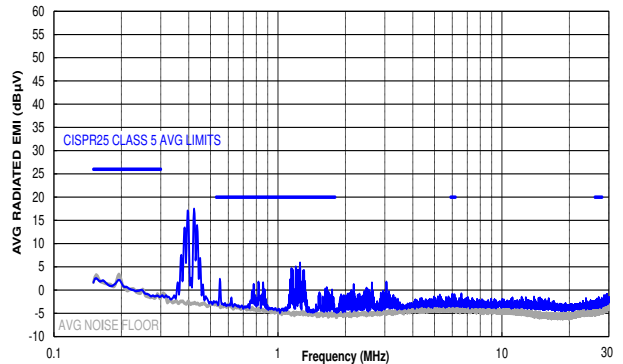
### CISPR25 Class 5 Peak Radiated Emissions

150kHz to 30MHz



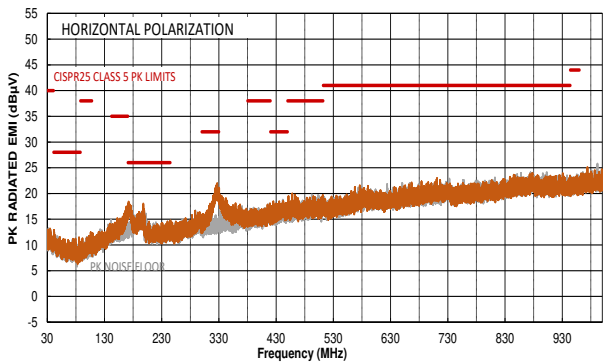
### CISPR25 Class 5 Average Radiated Emissions

150kHz to 30MHz



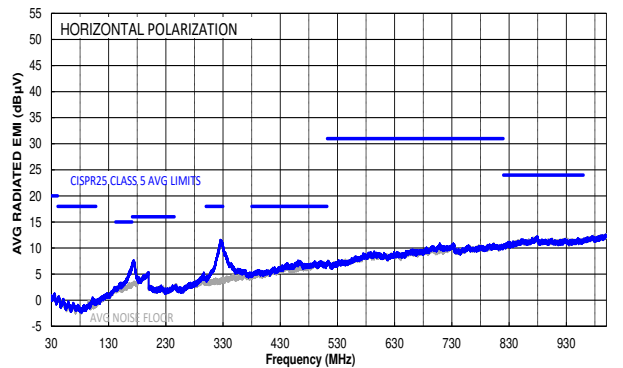
### CISPR25 Class 5 Peak Radiated Horizontal

30MHz to 1GHz



### CISPR25 Class 5 Average Radiated Horizontal

30MHz to 1GHz



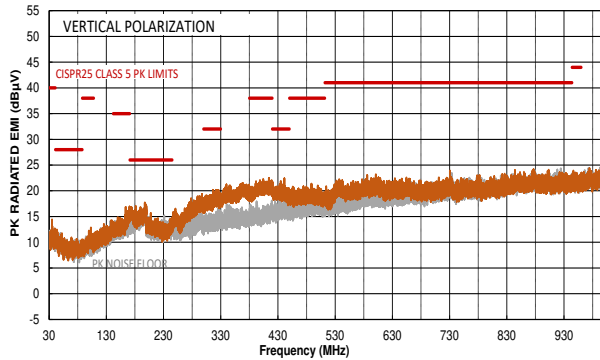


## TYPICAL PERFORMANCE CHARACTERISTICS *(continued)*

$V_{IN} = 12V$ ,  $V_{OUT} = 5V$ ,  $I_{OUT} = 6A$ ,  $L = 4.7\mu H$  <sup>(6)</sup>,  $f_{SW} = 410kHz$ ,  $T_A = 25^\circ C$ , unless otherwise noted. <sup>(7)</sup>

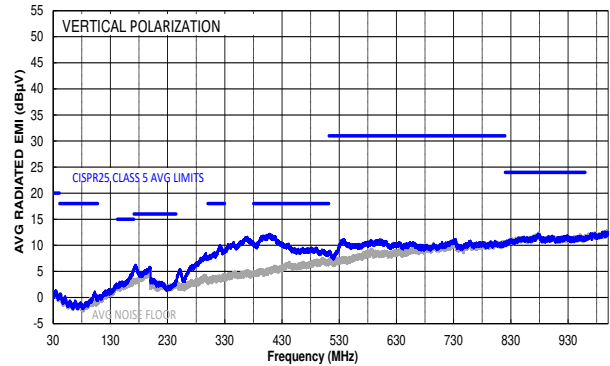
### CISPR25 Class 5 Peak Radiated Emissions

Vertical, 30MHz to 1GHz



### CISPR25 Class 5 Average Radiated Emissions

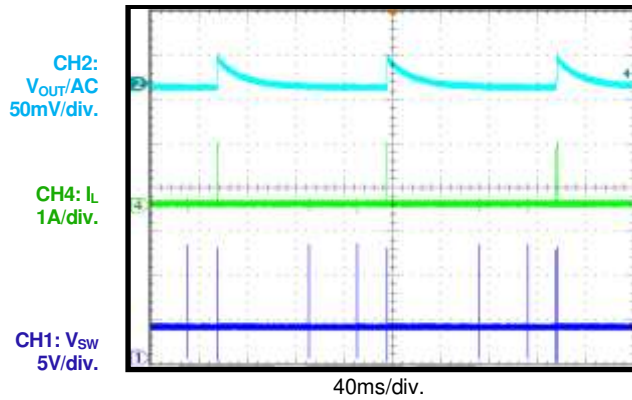
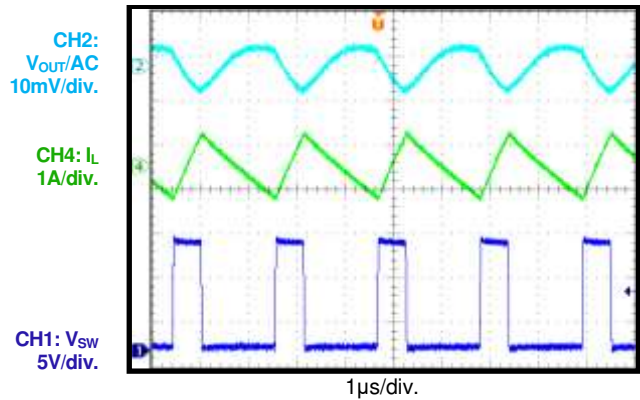
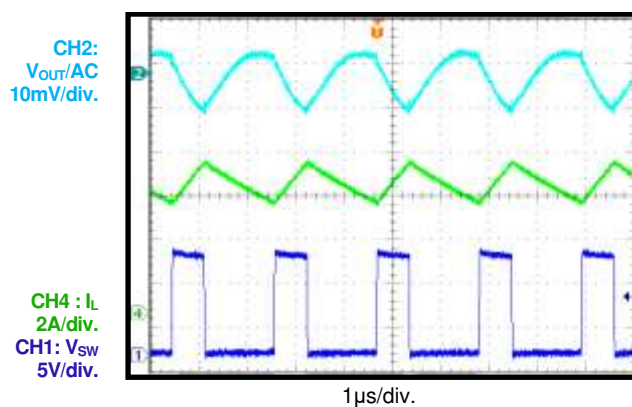
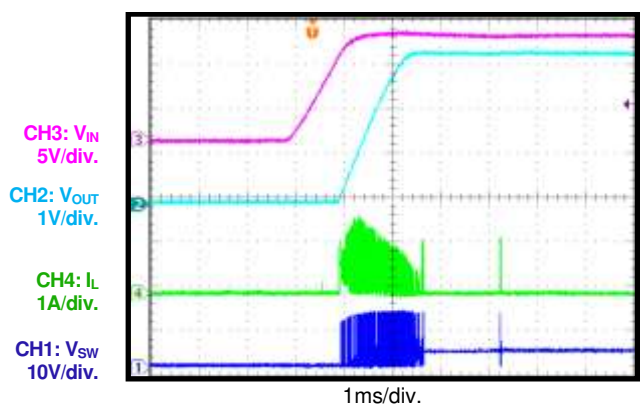
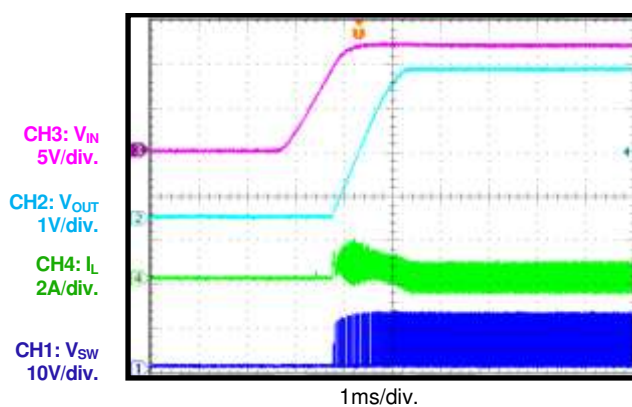
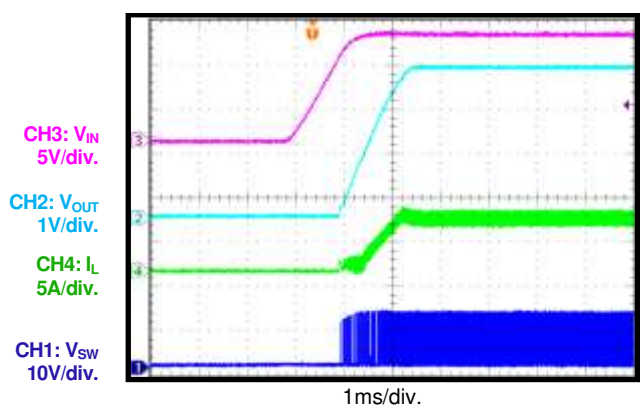
Vertical, 30MHz to 1GHz



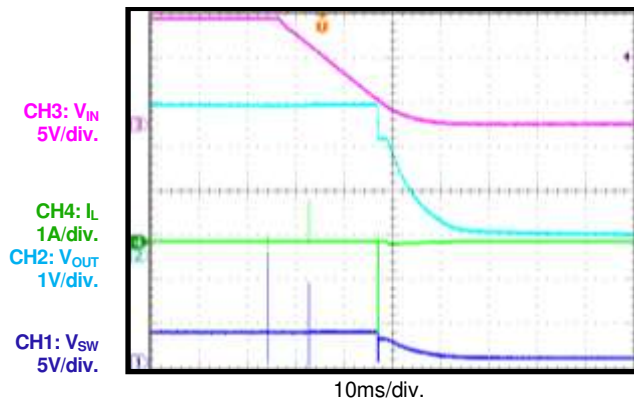
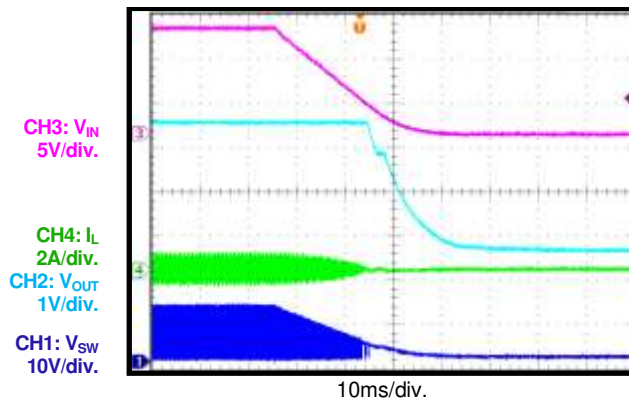
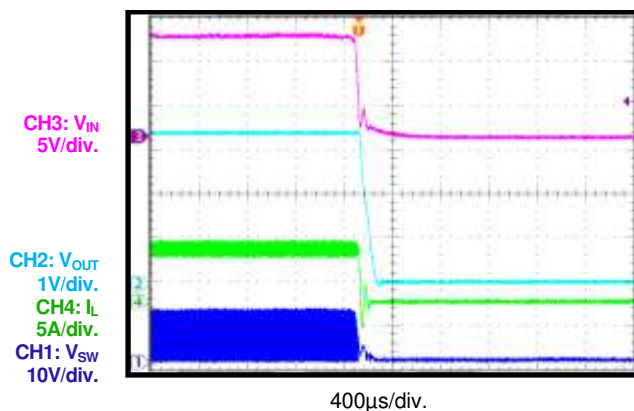
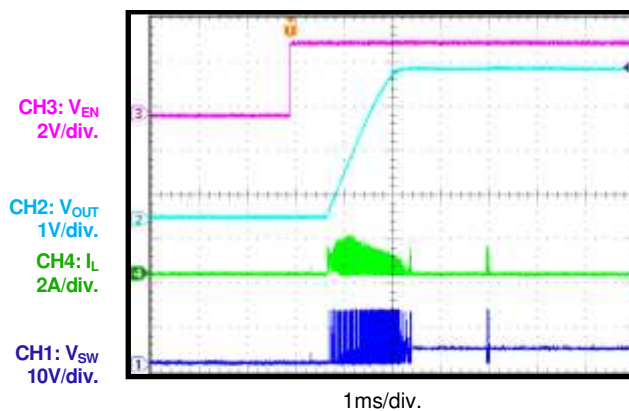
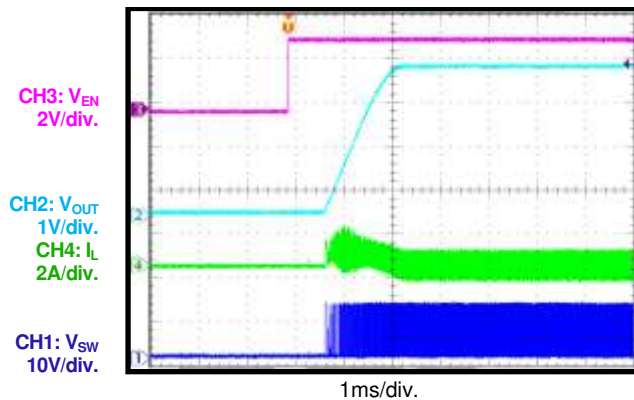
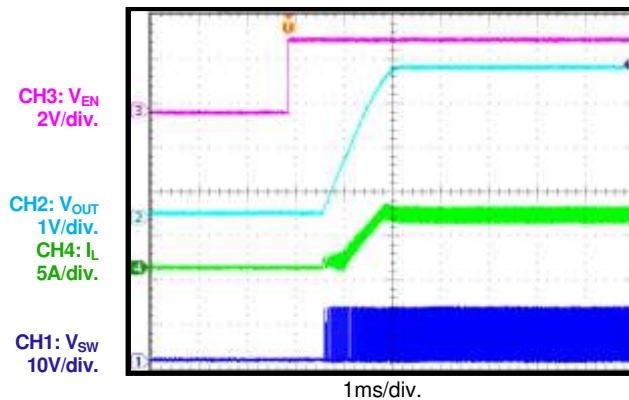
**Notes:**

- 6) Inductor part number: XAL6060-472MEC. DCR = 15mΩ.
- 7) The EMC test results are based on the application circuit with EMI filters (see Figure 11 on page 36).

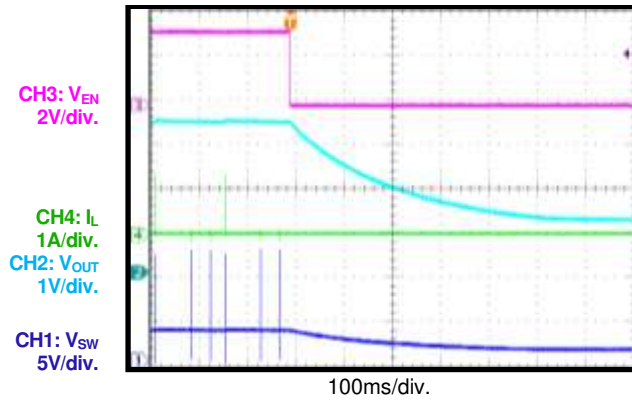
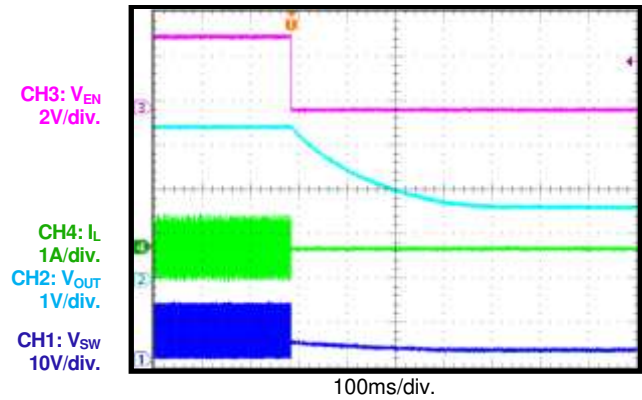
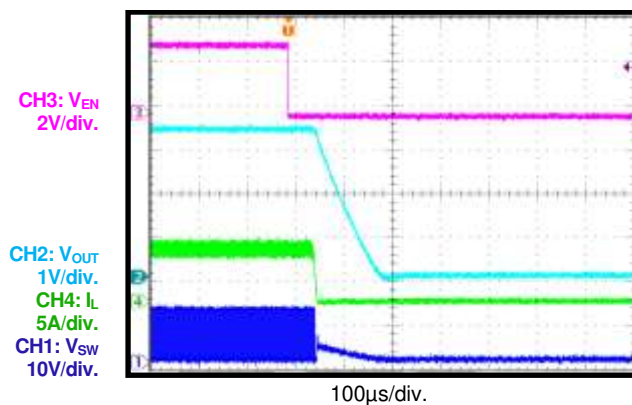
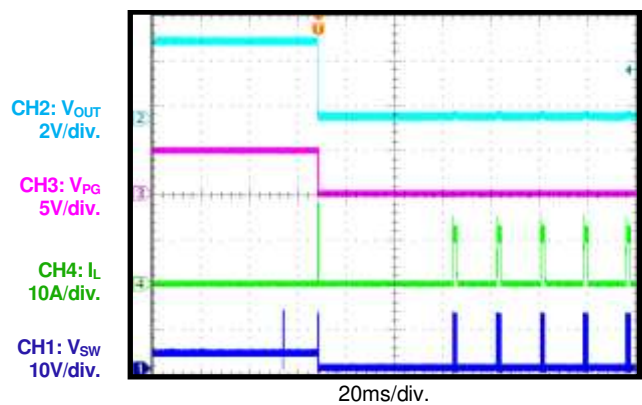
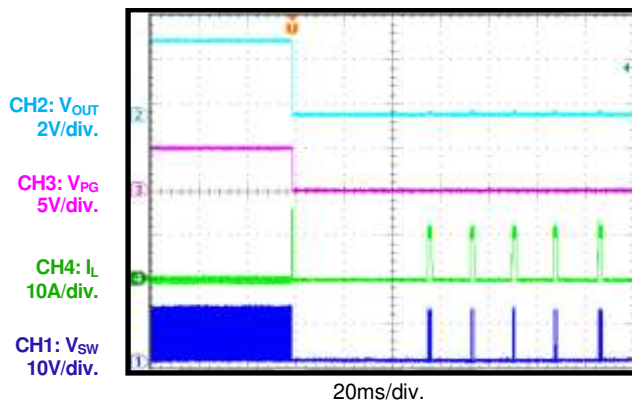
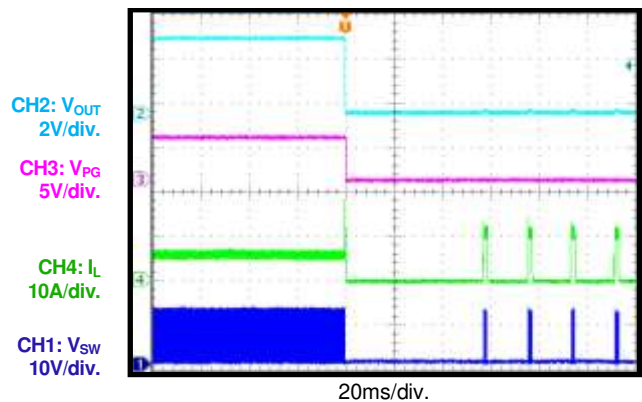
**TYPICAL PERFORMANCE CHARACTERISTICS (continued)**
 $V_{IN} = 12V$ ,  $V_{OUT} = 3.3V$ ,  $L = 4.7\mu H$ ,  $f_{SW} = 470kHz$ , AAM mode,  $T_A = 25^\circ C$ , unless otherwise noted.

**Steady State**
 $I_{OUT} = 0A$ , AAM mode

**Steady State**
 $I_{OUT} = 0A$ , FCCM

**Steady State**
 $I_{OUT} = 6A$ 

**Start-Up through VIN**
 $I_{OUT} = 0A$ , AAM mode

**Start-Up through VIN**
 $I_{OUT} = 0A$ , FCCM

**Start-Up through VIN**
 $I_{OUT} = 6A$ 


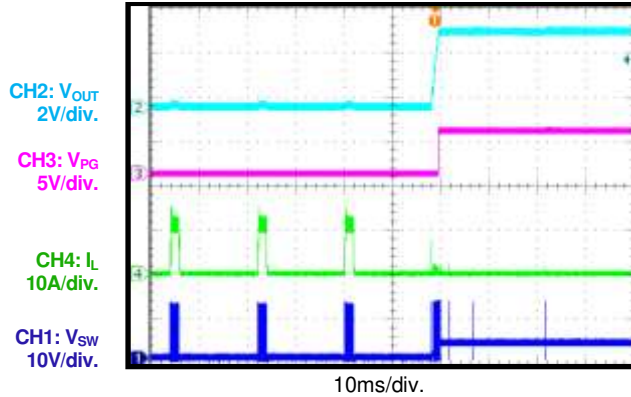
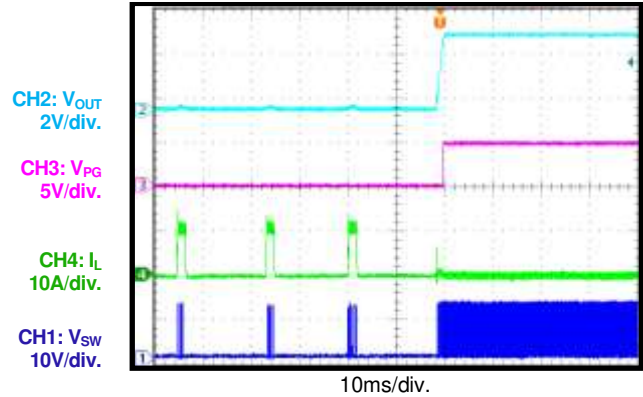
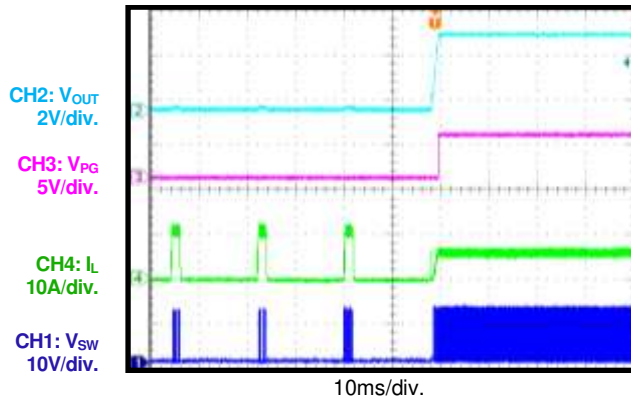
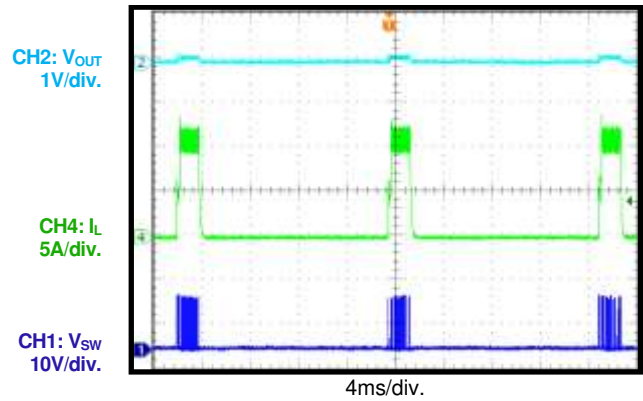
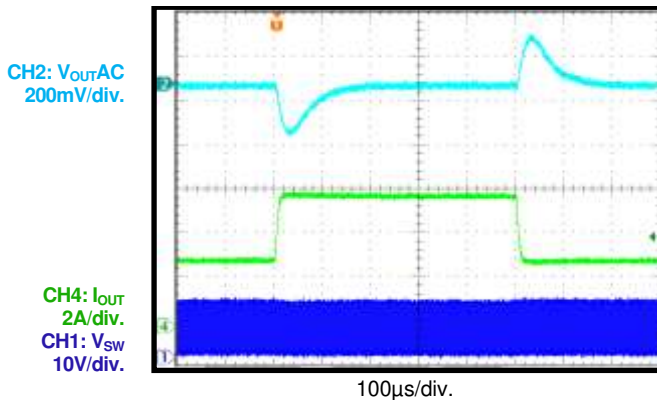
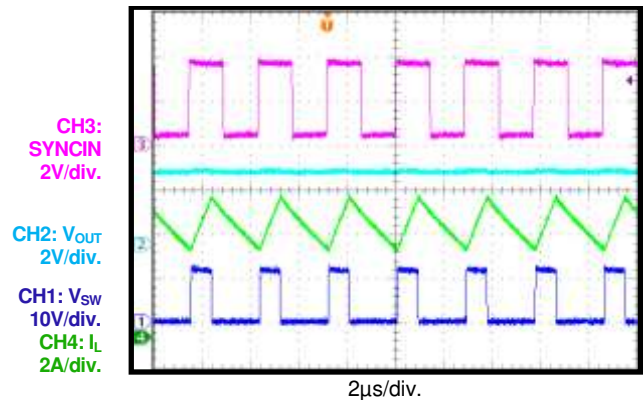
**TYPICAL PERFORMANCE CHARACTERISTICS (continued)**
 $V_{IN} = 12V$ ,  $V_{OUT} = 3.3V$ ,  $L = 4.7\mu H$ ,  $f_{SW} = 470kHz$ , AAM mode,  $T_A = 25^\circ C$ , unless otherwise noted.

**Shutdown through VIN**
 $I_{OUT} = 0A$ , AAM mode

**Shutdown through VIN**
 $I_{OUT} = 0A$ , FCCM

**Shutdown through VIN**
 $I_{OUT} = 6A$ 

**Start-Up through EN**
 $I_{OUT} = 0A$ , AAM mode

**Start-Up through EN**
 $I_{OUT} = 0A$ , FCCM

**Start-Up through EN**
 $I_{OUT} = 6A$ 


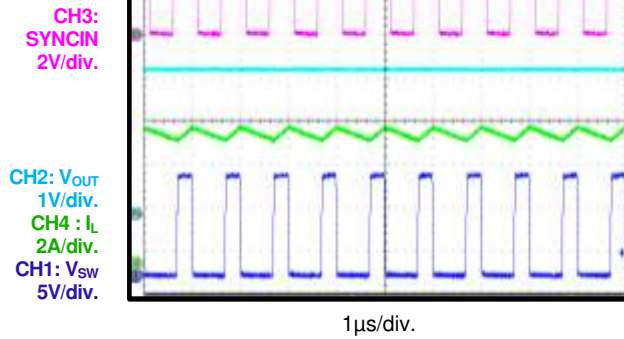
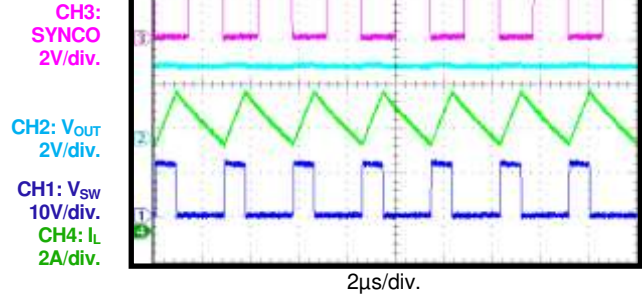
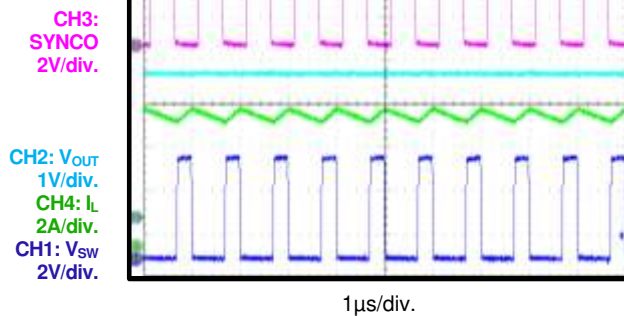
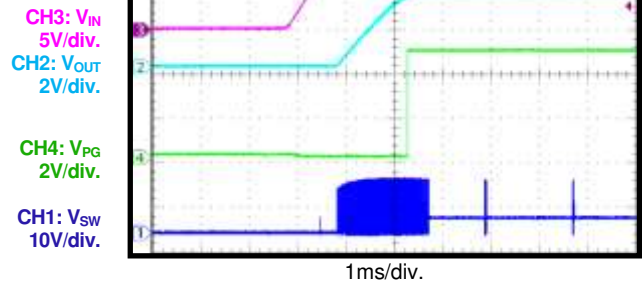
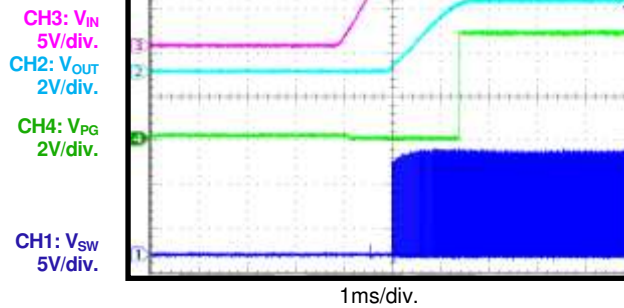
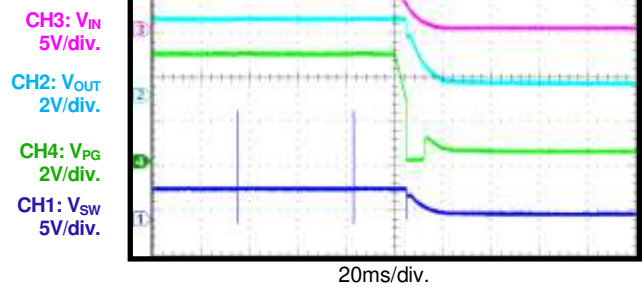
**TYPICAL PERFORMANCE CHARACTERISTICS (continued)**
 $V_{IN} = 12V$ ,  $V_{OUT} = 3.3V$ ,  $L = 4.7\mu H$ ,  $f_{SW} = 470kHz$ , AAM mode,  $T_A = 25^\circ C$ , unless otherwise noted.

**Shutdown through EN**
 $I_{OUT} = 0A$ , AAM mode

**Shutdown through EN**
 $I_{OUT} = 0A$ , FCCM

**Shutdown through EN**
 $I_{OUT} = 6A$ 

**SCP Entry**
 $I_{OUT} = 0A$ , AAM mode

**SCP Entry**
 $I_{OUT} = 0A$ , FCCM

**SCP Entry**
 $I_{OUT} = 6A$ 


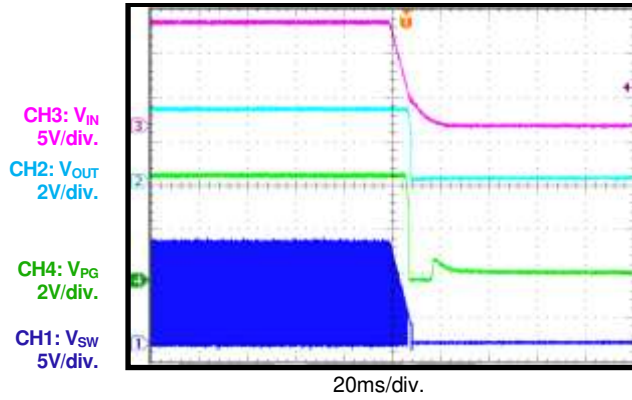
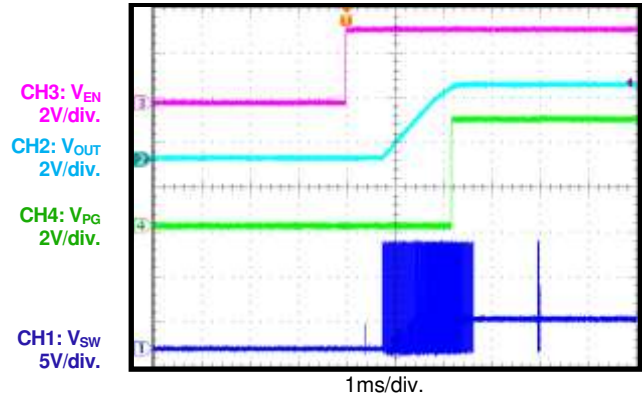
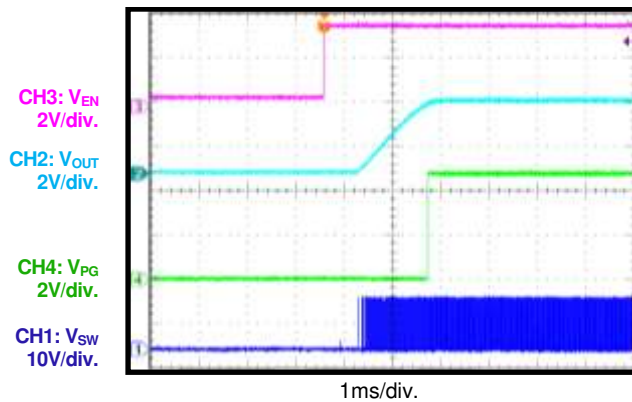
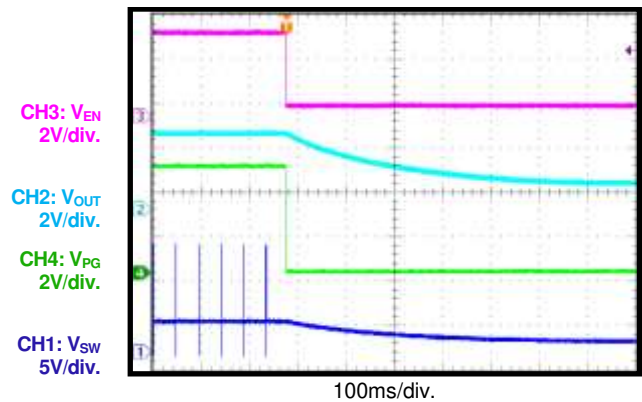
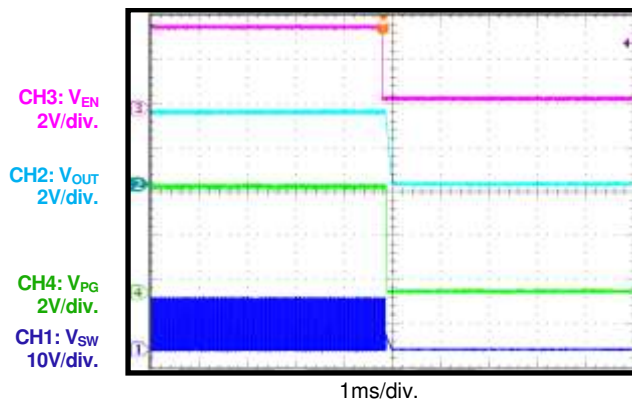
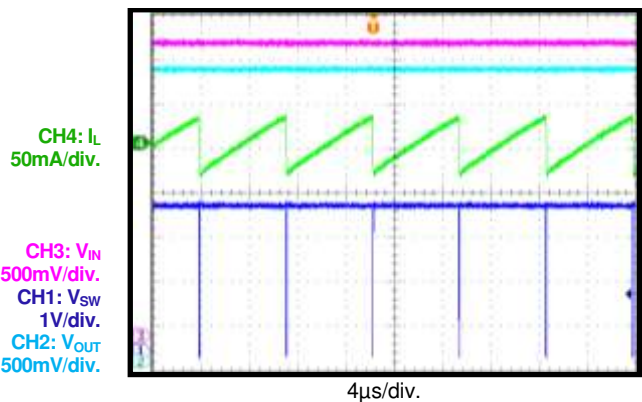
**TYPICAL PERFORMANCE CHARACTERISTICS (continued)**
 $V_{IN} = 12V$ ,  $V_{OUT} = 3.3V$ ,  $L = 4.7\mu H$ ,  $f_{SW} = 470kHz$ , AAM mode,  $T_A = 25^\circ C$ , unless otherwise noted.

**SCP Recovery**
 $I_{OUT} = 0A$ , AAM mode

**SCP Recovery**
 $I_{OUT} = 0A$ , FCCM

**SCP Recovery**
 $I_{OUT} = 6A$ 

**SCP Steady State**

**Load Transient**
 $I_{OUT} = 3A$  to  $6A$ ,  $1.6A/\mu s$ 

**SYNCIN Operation**
 $I_{OUT} = 6A$ , SYNC frequency = 350kHz


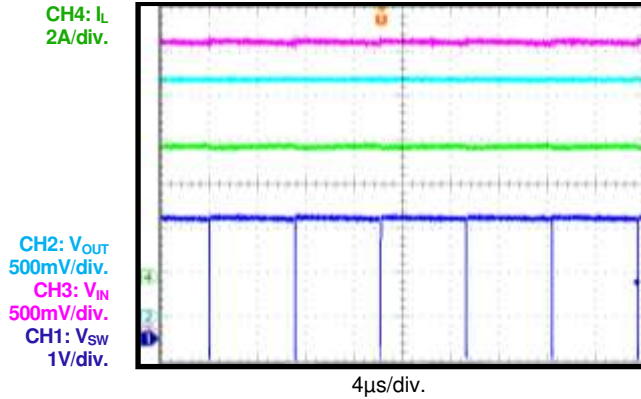
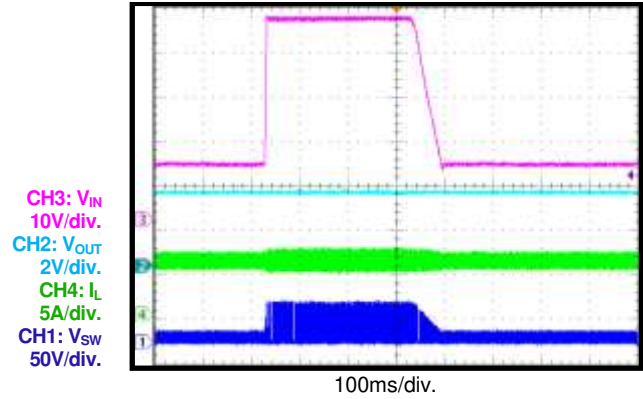
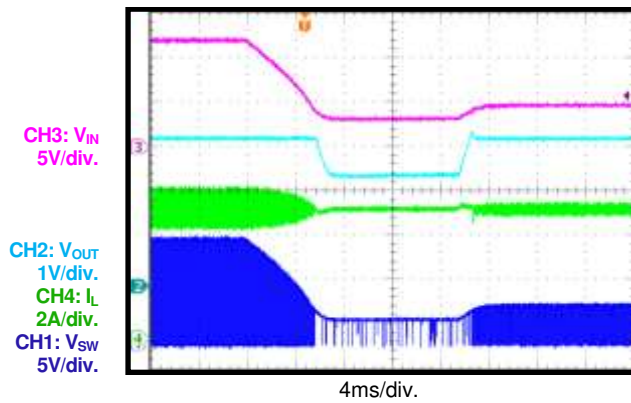
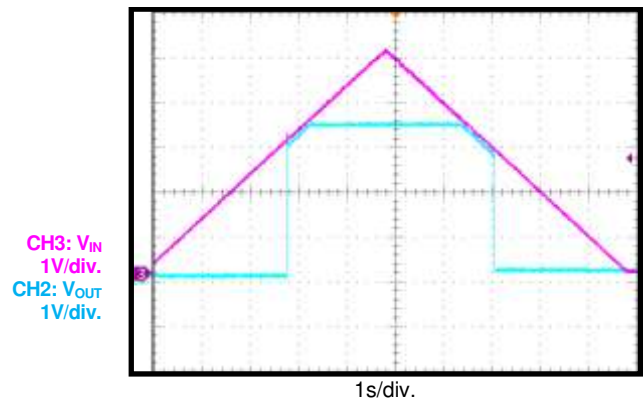
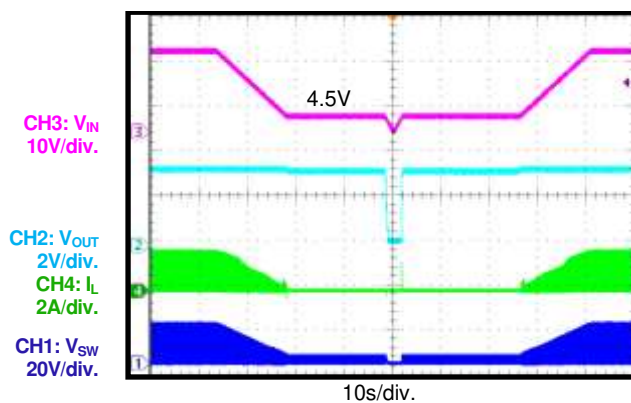
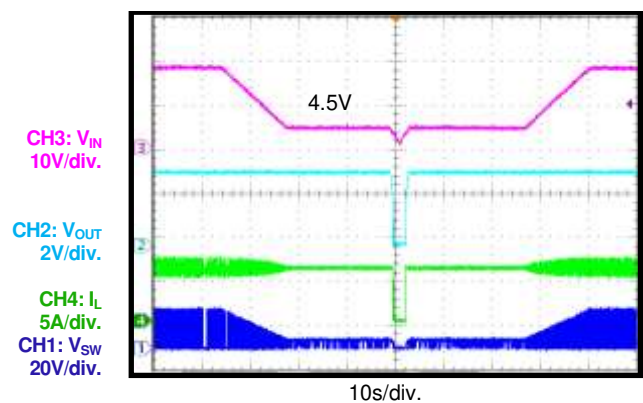
**TYPICAL PERFORMANCE CHARACTERISTICS (continued)**
 $V_{IN} = 12V$ ,  $V_{OUT} = 3.3V$ ,  $L = 4.7\mu H$ ,  $f_{SW} = 470kHz$ , AAM mode,  $T_A = 25^\circ C$ , unless otherwise noted.

**SYNCIN Operation**
 $I_{OUT} = 6A$ , SYNC frequency = 1000kHz

**SYNCO Operation**
 $I_{OUT} = 6A$ , SYNC frequency = 350kHz

**SYNCO Operation**
 $I_{OUT} = 6A$ , SYNC frequency = 1000kHz

**PG Start-Up through VIN**
 $I_{OUT} = 0A$ 

**PG Start-Up through VIN**
 $I_{OUT} = 6A$ 

**PG Shutdown through VIN**
 $I_{OUT} = 0A$ 


**TYPICAL PERFORMANCE CHARACTERISTICS (continued)**
 $V_{IN} = 12V$ ,  $V_{OUT} = 3.3V$ ,  $L = 4.7\mu H$ ,  $f_{SW} = 470kHz$ , AAM mode,  $T_A = 25^\circ C$ , unless otherwise noted.

**PG Shutdown through VIN**
 $I_{OUT} = 6A$ 

**PG Start-Up through EN**
 $I_{OUT} = 0A$ 

**PG Start-Up through EN**
 $I_{OUT} = 6A$ 

**PG Shutdown through EN**
 $I_{OUT} = 0A$ 

**PG Shutdown through EN**
 $I_{OUT} = 6A$ 

**Low-Dropout Mode**
 $V_{IN} = 3.3V$ ,  $V_{OUT}$  set to 3.3V,  $I_{OUT} = 0A$ 


**TYPICAL PERFORMANCE CHARACTERISTICS (continued)**
 $V_{IN} = 12V$ ,  $V_{OUT} = 3.3V$ ,  $L = 4.7\mu H$ ,  $f_{SW} = 470kHz$ , AAM mode,  $T_A = 25^\circ C$ , unless otherwise noted.

**Low-Dropout Mode**
 $V_{IN} = 3.3V$ ,  $V_{OUT}$  set to 3.3V,  $I_{OUT} = 6A$ 

**Load Dump**
 $V_{IN} = 12V$  to 36V,  $I_{OUT} = 6A$ 

**Cold Crank**
 $V_{IN} = 12V$  to 3.3V to 5V,  $I_{OUT} = 6A$ 

 **$V_{IN}$  Ramping Up and Down**
 $I_{OUT} = 0.1A$ 

 **$V_{IN}$  Ramping Down and Up**
 $I_{OUT} = 1mA$ 

 **$V_{IN}$  Ramping Down and Up**
 $I_{OUT} = 6A$ 




## FUNCTIONAL BLOCK DIAGRAM

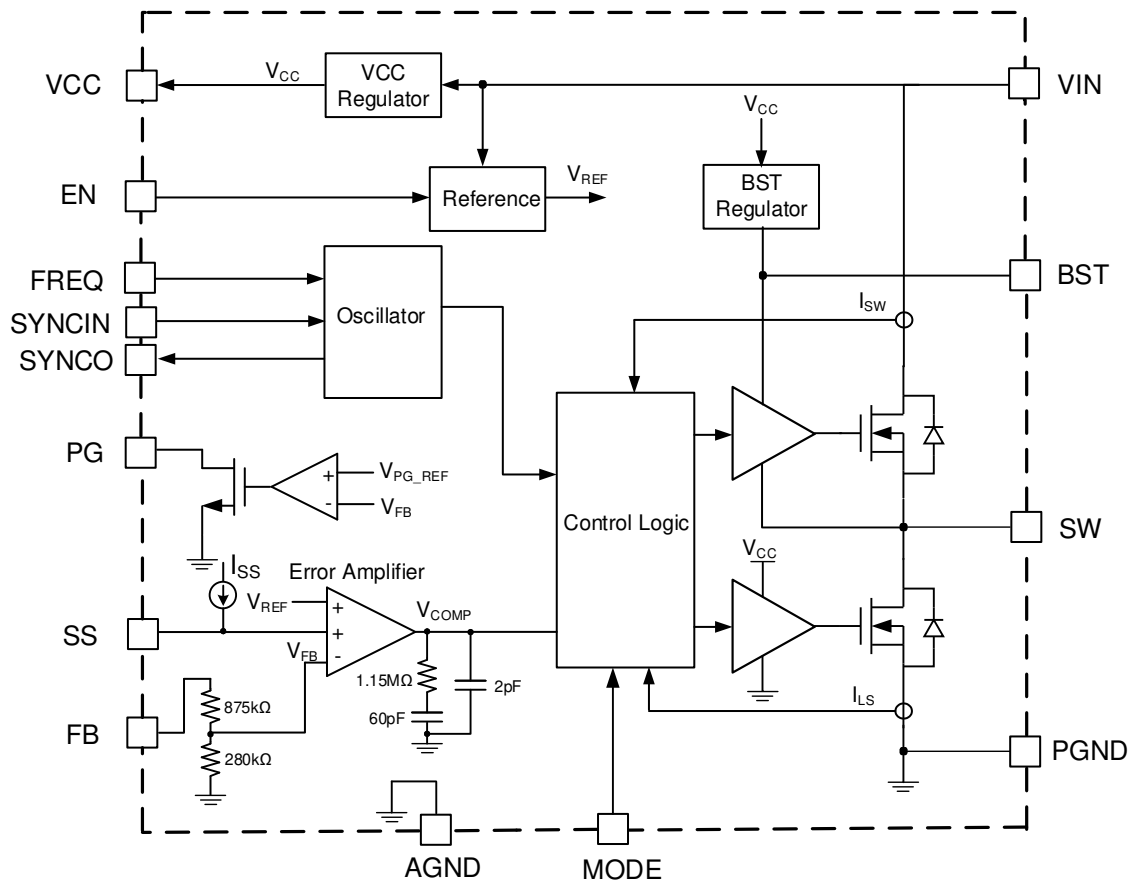
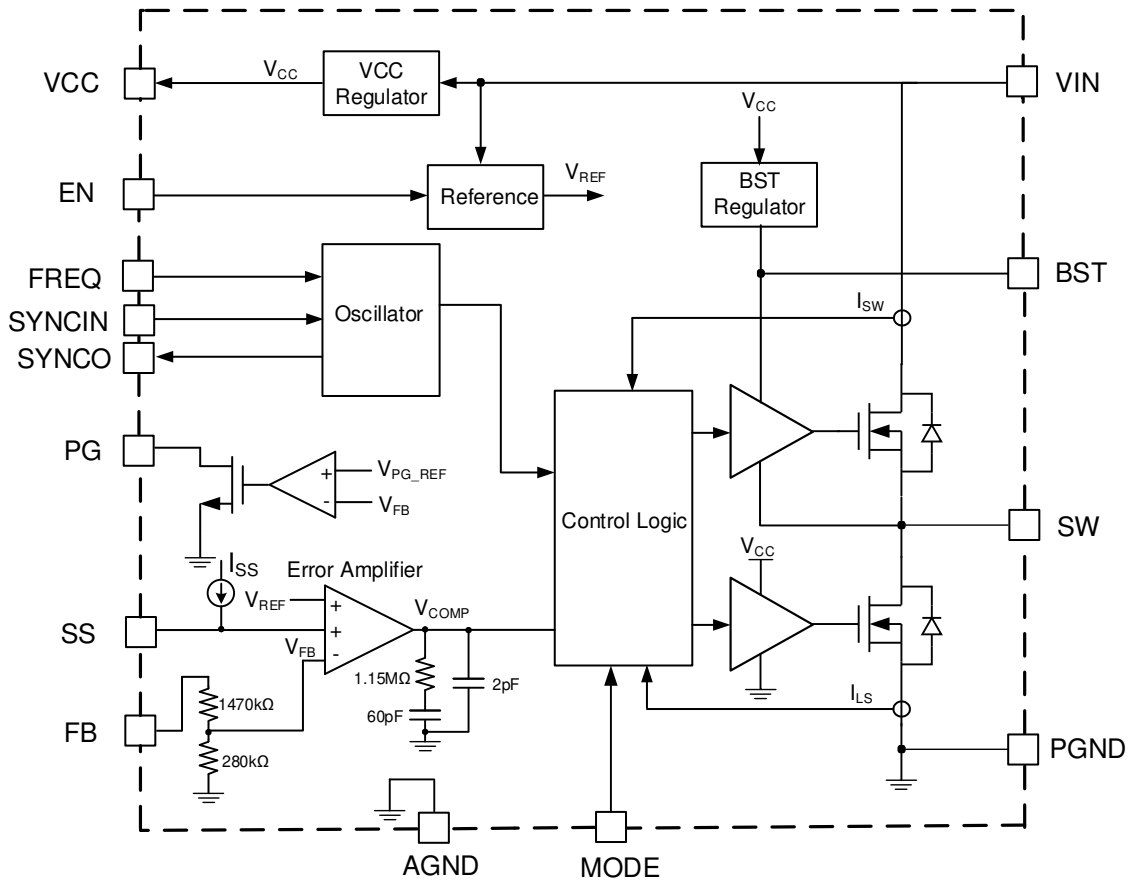


Figure 1: Functional Block Diagram (3.3V Fixed Output Version)

**FUNCTIONAL BLOCK DIAGRAM (continued)**



**Figure 2: Functional Block Diagram (5V Fixed Output Version)**

### Timing Sequence

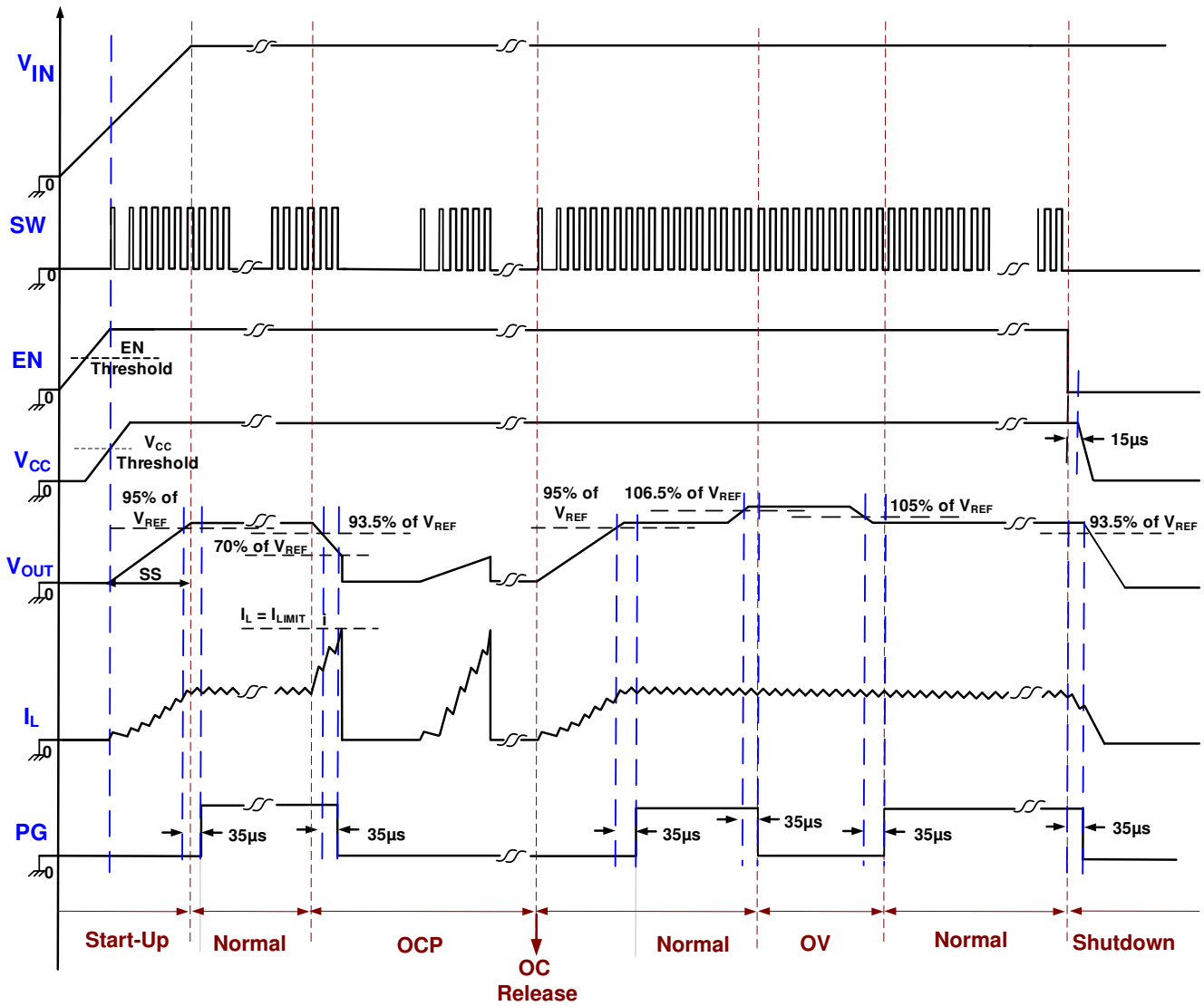


Figure 3: Timing Sequence

## OPERATION

The MPQ4436A is a synchronous, step-down switching regulator with integrated internal high-side and low-side power MOSFETs (HS-FET and LS-FET, respectively). It provides 6A of highly efficient output current ( $I_{OUT}$ ) with current mode control.

It features a wide input voltage ( $V_{IN}$ ) range, configurable switching frequency ( $f_{SW}$ ), external soft start (SS), and precision current limiting. Its very low operational quiescent current ( $I_Q$ ) makes it ideal for battery-powered applications.

### Pulse-Width Modulation (PWM) Control

At moderate to high output currents, the MPQ4436A operates in fixed-frequency, peak current control mode to regulate the output voltage ( $V_{OUT}$ ). A PWM cycle is initiated by the internal clock. At the rising edge of the clock, the HS-FET turns on and remains on until its current reaches the value set by the internal COMP voltage ( $V_{COMP}$ ). Once the HS-FET is on, it remains on for at least 100ns.

When the HS-FET is off, the LS-FET turns on immediately and remains on until the next cycle starts. Once the LS-FET is on, it remains on for at least 80ns before next cycle starts.

If the current in the HS-FET does not reach the COMP-set current value within one PWM period, then the HS-FET remains on, saving a turn-off operation. If the on time lasts about 10 $\mu$ s, then the HS-FET is forced off even though COMP is not reached.

### Light-Load Operation

Under light-load conditions, the MPQ4436A can work in two different operation modes by setting the MODE pin to one of two different statuses.

The MPQ4436A works in forced continuous conduction mode (FCCM) when the MODE pin is pulled above 1.8V. In this mode, the part works with a fixed frequency from no load to full load. The advantage of FCCM is the controllable frequency and lower output ripple at light loads.

The MPQ4436A works in asynchronous advanced modulation (AAM) mode when the MODE pin is pulled below 0.4V. AAM is meant to optimize the efficiency during light-load and no-load conditions.

When AAM mode is enabled, the MPQ4436A first enters asynchronous operation as long as the inductor current ( $I_L$ ) approaches 0A at light load. If the load is further decreased or there is no load that makes  $V_{COMP}$  decrease to the set value, the MPQ4436A enters AAM mode. In AAM mode, the internal clock is reset every time  $V_{COMP}$  crosses over the set value. The crossover time is taken as the benchmark of the next clock. When the load increases and  $V_{COMP}$  exceeds the set value, the operation mode is discontinuous conduction mode (DCM) or CCM, which has a constant  $f_{SW}$  (see Figure 4).

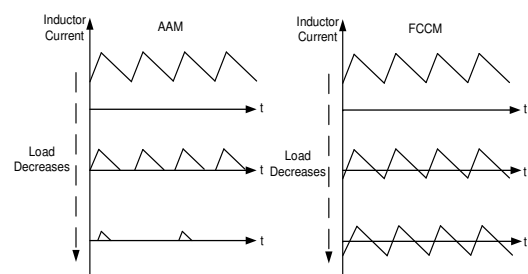


Figure 4: AAM and FCCM

### Error Amplifier (EA)

The error amplifier (EA) compares the FB pin's voltage ( $V_{FB}$ ) with the internal reference voltage ( $V_{REF}$ , typically 0.815V) and outputs a current proportional to the difference between the two. This current is then used to charge the compensation network to form  $V_{COMP}$ , which is used to control the power MOSFET current.

During operation, the minimum  $V_{COMP}$  is clamped to 0.9V, and the maximum  $V_{COMP}$  is clamped to 2V. COMP is internally pulled down to GND in shutdown mode.

### Internal VCC Regulator

Most of the internal circuitry is powered by the internal 4.9V VCC regulator. This regulator takes  $V_{IN}$  as the input and operates across the full  $V_{IN}$  range. When  $V_{IN}$  exceeds 4.9V, VCC is in full regulation. When  $V_{IN}$  is below this point, the output VCC voltage ( $V_{CC}$ ) degrades.

### Bootstrap (BST) Charging

The bootstrap (BST) capacitor ( $C_{BST}$ ) is charged and regulated to about 5V by the dedicated internal BST regulator. When the voltage between the BST and SW nodes is below its

regulation value, a PMOS pass transistor connected from VCC to BST turns on to charge  $C_{BST}$ . External circuitry should provide enough voltage headroom to facilitate charging. When the HS-FET is on, BST is above VCC, so  $C_{BST}$  cannot be charged.

At higher duty cycles, the time period available for BST charging is shorter, so  $C_{BST}$  may not be charged sufficiently. If the external circuit has not had sufficient voltage and time to charge  $C_{BST}$ , extra external circuitry can be used to ensure that the bootstrap voltage ( $V_{BST}$ ) is within the normal operation range.

### Low-Dropout Mode and BST Refresh

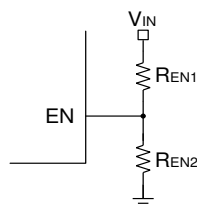
To improve dropout, the MPQ4436A is designed to operate at close to 100% duty cycle as long as the BST-to-SW voltage is greater than 2.5V. When the voltage from BST to SW drops below 2.5V, the HS-FET turns off using an under-voltage lockout (UVLO) circuit, which allows the LS-FET to conduct and refresh the charge on  $C_{BST}$ . In DCM or pulse-skip mode (PSM), the LS-FET is forced on to refresh  $V_{BST}$ .

Since the supply current sourced from  $C_{BST}$  is low, the HS-FET remains on for more switching cycles than are required to refresh the capacitor. Therefore, the effective duty cycle of the switching regulator is high.

The effective duty cycle during dropout of the regulator is mainly influenced by the voltage drops across the power MOSFET, inductor resistance, the low-side diode, and PCB resistance.

### Enable (EN) Control

EN is a digital control pin that turns the regulator on and off (see Figure 5).



**Figure 5: Enable Divider Circuit**

It offers two main features:

1. EN is enabled by an external logic (H/L) signal. When EN is pulled below the falling voltage threshold (0.85V), the chip is put into the lowest shutdown current mode. Forcing

this pin above the EN rising threshold voltage (1V) turns on the part.

2. EN can configure  $V_{IN}$  UVLO. With high enough  $V_{IN}$ , the chip can be enabled and disabled by the EN pin. This pin can generate a configurable  $V_{IN}$  UVLO and hysteresis.

### Frequency Programmable and Foldback

The MPQ4436A's oscillating frequency is programmed either by an external resistor ( $R_{FREQ}$ ) from the FREQ pin to ground, or by a logic-level SYNC signal. To get an expected  $f_{SW}$  select the  $R_{FREQ}$  value following the  $f_{SW}$  vs.  $R_{FREQ}$  curve (see the Typical Performance Characteristics section on page 15).

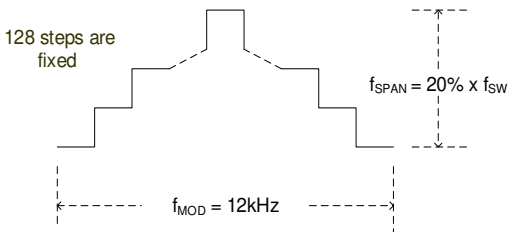
When  $f_{SW}$  is high, it folds back at high input voltages to avoid triggering the minimum on time ( $t_{ON\_MIN}$ ) and the output going out of regulation. The recommended  $f_{SW}$  range for car battery applications is 350kHz to 1000kHz. Table 1 lists the recommended  $R_{FREQ}$  values for common frequencies. Higher frequencies can be used in applications that do not have a critical  $f_{SW}$  limit, as well as applications with a low, stable  $V_{IN}$ .

**Table 1:  $R_{FREQ}$  vs.  $f_{SW}$**

$R_{FREQ}$ (k $\Omega$ )	$f_{SW}$ (kHz)
86.6	350
80.6	380
75	410
62	470
59	500
54.9	530
49.9	590
45.3	640
41.2	700
37.4	760
34	830
30.9	910
28.7	960
26.1	1000

### Frequency Spread Spectrum (FSS)

The MPQ4436A uses a 12kHz modulation frequency with a 128-step triangular profile to spread the internal oscillator frequency over a 20% ( $\pm 10\%$ ) window (see Figure 6 on page 30). The steps are fixed and independent of the set oscillator frequency to optimize frequency spread spectrum (FSS) performance.


**Figure 6: Spread Spectrum Scheme**

### Soft Start (SS)

Soft start (SS) is implemented to prevent the converter's  $V_{OUT}$  from overshooting during start-up.

When the soft-start time ( $t_{SS}$ ) starts, an internal current source begins charging the external soft-start capacitor ( $C_{SS}$ ). When the soft-start voltage ( $V_{SS}$ ) falls below the  $V_{REF}$ ,  $V_{SS}$  overrides  $V_{REF}$  and the EA uses  $V_{SS}$  as the reference. When  $V_{SS}$  exceeds  $V_{REF}$ ,  $V_{REF}$  is used as the reference.  $C_{SS}$  can be calculated with Equation (1):

$$C_{SS}(\text{nF}) = \frac{t_{SS}(\text{ms}) \times I_{SS}(\mu\text{A})}{V_{REF}(\text{V})} = 6.25 \times t_{SS}(\text{ms}) \quad (1)$$

The SS pins can be used for tracking and sequencing.

### Pre-Biased Start-Up

For the MPQ4436A, if  $V_{FB} > V_{SS} - 150\text{mV}$  at start-up (which means the output has a pre-biased voltage), neither the HS-FET nor LS-FET are turned on until  $V_{SS}$  exceeds  $V_{FB}$ .

### Thermal Shutdown

Thermal shutdown is implemented to prevent the chip from thermally running away. If the silicon die temperature exceeds its upper threshold ( $170^\circ\text{C}$ ), the power MOSFETs shut down. When the temperature falls below its lower threshold ( $150^\circ\text{C}$ ), the chip is enabled again.

### Current Comparator and Current Limit

The power MOSFET current is accurately sensed via a current-sense MOSFET. It is then fed to the high-speed current comparator for current mode control. The current comparator takes this sensed current as one of its inputs.

When the HS-FET turns on, the comparator is blanked until the end of the turn-on transition to avoid noise. Then the comparator compares the power MOSFET current with  $V_{COMP}$ . When the sensed current exceeds  $V_{COMP}$ , the comparator outputs low to turn off the HS-FET. The internal

power MOSFET's maximum current is internally limited cycle by cycle.

### Hiccup Protection

If the output is shorted to ground, causing  $V_{OUT}$  to drop below 70% of its nominal voltage, the IC shuts down momentarily and begins discharging  $C_{SS}$ . It restarts with a full SS when  $C_{SS}$  is fully discharged. This hiccup process repeats until the fault condition is removed.

### Start-Up and Shutdown

If both  $V_{IN}$  and EN exceed their respective thresholds, the chip starts. The reference block starts first, generating a stable reference voltage and currents, and then the internal regulator is enabled. The regulator provides a stable supply for the remaining circuitries.

While the internal supply rail is up, an internal timer holds the power MOSFET off for about  $50\mu\text{s}$  to blank any start-up glitches. When the SS block is enabled, it first holds  $V_{SS}$  low to ensure the remaining circuitries are ready, then slowly ramps up.

Three events can shut down the chip: EN going low,  $V_{IN}$  going low, and thermal shutdown. During the shutdown procedure, the signaling path is blocked first to avoid any fault triggering.  $V_{COMP}$  and the internal supply rail are then pulled down. The floating driver is not subject to this shutdown command, but its charging path is disabled.

### Power Good (PG) Output

The MPQ4436A includes an open-drain power good (PG) output that indicates the output. A pull-up resistor connected to the power source is required if PG is used. If  $V_{OUT}$  is within 95% to 105% of the nominal voltage, the PG pin goes high. If  $V_{OUT}$  is above 106.5% or below 93.5% of the nominal voltage, PG goes low.

### SYNCIN and SYNCO

$f_{SW}$  can be synced to the rising edge of the clock signal applied at SYNCIN. The recommended SYNCIN frequency range is 350kHz to 1000kHz. Ensure that the SYNCIN off time is shorter than the internal oscillator period; otherwise the internal clock may turn on the HS-FET before the rising edge of SYNCIN. There is no other special limit on the pulse width of SYNCIN, but there is always parasitic capacitance of the pad. If the pulse width is too short, a clear rising and falling

edge may not be seen due to the parasitic capacitance. A pulse longer than 100ns is recommended in most application .

When applying SYNCIN in AAM mode, pull SYNCIN below its threshold (0.4V) or leave SYNCIN floating before the MPQ4436A starts up, and then adding external SYNCIN clock.

To avoid floating SYNCIN when using this function through an external clock, connect a resistor to GND. Considering SYNCIN's drive

capability, it is recommended to use a 10kΩ to 51kΩ resistor.

The SYNCO pin provides a default 180° phase-shifted clock to the internal oscillator. If there is no external SYNCIN clock, then SYNCO provides a 180° phase-shifted clock that is compared to the internal clock. If there is an external SYNCIN clock, then SYNCO provides a 180° phase-shifted clock that is compared to the external SYNCIN clock.

## APPLICATION INFORMATION

### Setting the BST Capacitor

If using the MPQ4436A in CCM mode only, use a BST capacitor ( $C_{BST}$ ) with a nominal capacitance of at least  $0.2\mu\text{F}$ . If using AAM mode, the external  $C_{BST}$  should be greater than  $0.2\mu\text{F}$ . Alternately, choose  $C_{BST}$  using Equation (2) and Equation (3):

$$C_{BST} (\mu\text{F}) \geq \frac{75 \times C_{OUT} (\mu\text{F}) \times 10^{-3}}{I_{MIN} (\mu\text{A})} \quad (2)$$

$$C_{BST} (\mu\text{F}) \geq \frac{80}{I_{MIN} (\mu\text{A}) \times L (\mu\text{H})} \quad (3)$$

If the calculated  $C_{BST}$  is greater than  $6.8\mu\text{F}$ , contact an MPS FAE to verify the design.

### Setting the VCC Capacitor

The VCC capacitor should be 10 times the value of the boost capacitor, and at least  $4.7\mu\text{F}$  nominal. A VCC capacitor greater than  $68\mu\text{F}$  nominal is not recommended.

### Selecting the Input Capacitor

The step-down converter has a discontinuous input current, and requires a capacitor to supply AC current to the converter while maintaining the DC input voltage. For the best performance, use low-ESR capacitors. Ceramic capacitors with X5R or X7R dielectrics are highly recommended because of their low ESR and small temperature coefficients.

For most applications, it is recommended to use a  $4.7\mu\text{F}$  to  $10\mu\text{F}$  capacitor. It is strongly recommended to use another, lower-value capacitor (e.g.  $0.1\mu\text{F}$ ) with a small package size (0603) to absorb high-frequency switching noise. Place the smaller capacitor as close to  $V_{IN}$  and GND as possible.

Since  $C_{IN}$  absorbs the input switching current, it requires an adequate ripple current rating. The RMS current ( $I_{CIN}$ ) in the input capacitor can be estimated with Equation (4):

$$I_{CIN} = I_{LOAD} \times \sqrt{\frac{V_{OUT}}{V_{IN}} \times \left(1 - \frac{V_{OUT}}{V_{IN}}\right)} \quad (4)$$

The worst-case condition occurs at  $V_{IN} = 2 \times V_{OUT}$ , calculated with Equation (5):

$$I_{CIN} = \frac{I_{LOAD}}{2} \quad (5)$$

For simplification, choose an input capacitor with an RMS current rating greater than half of the maximum load current.

The input capacitor can be electrolytic, tantalum, or ceramic. When using electrolytic or tantalum capacitors, add a small, high-quality ceramic capacitor (e.g.  $0.1\mu\text{F}$ ) as close to the IC as possible. When using ceramic capacitors, ensure that they have enough capacitance to provide a sufficient charge to prevent excessive voltage ripple at the input. The input voltage ripple ( $\Delta V_{IN}$ ) caused by the capacitance can be estimated with Equation (6):

$$\Delta V_{IN} = \frac{I_{LOAD}}{f_{SW} \times C_{IN}} \times \frac{V_{OUT}}{V_{IN}} \times \left(1 - \frac{V_{OUT}}{V_{IN}}\right) \quad (6)$$

### Selecting the Output Capacitor

The output capacitor maintains the DC output voltage. Use ceramic, tantalum, or low-ESR electrolytic capacitors. For best results, use low-ESR capacitors to keep the output voltage ripple low. The output voltage ripple can be estimated with Equation (7):

$$\Delta V_{OUT} = \frac{V_{OUT}}{f_{SW} \times L} \times \left(1 - \frac{V_{OUT}}{V_{IN}}\right) \times \left(R_{ESR} + \frac{1}{8f_{SW} \times C_{OUT}}\right) \quad (7)$$

Where  $L$  is the inductance, and  $R_{ESR}$  is the equivalent series resistance (ESR) value of the output capacitor.

For ceramic capacitors, the capacitance dominates the impedance at the switching frequency and causes the majority of the output voltage ripple. For simplification, the output voltage ripple ( $\Delta V_{OUT}$ ) can be estimated with Equation (8):

$$\Delta V_{OUT} = \frac{V_{OUT}}{8 \times f_{SW}^2 \times L \times C_{OUT}} \times \left(1 - \frac{V_{OUT}}{V_{IN}}\right) \quad (8)$$

For tantalum or electrolytic capacitors, the ESR dominates the impedance at the switching frequency. For simplification, the output ripple can be estimated with Equation (9):

$$\Delta V_{OUT} = \frac{V_{OUT}}{f_{SW} \times L} \times \left(1 - \frac{V_{OUT}}{V_{IN}}\right) \times R_{ESR} \quad (9)$$



The characteristics of the output capacitor also affect the stability of the regulation system. The MPQ4436A can be optimized for a wide range of capacitance and ESR values.

### Selecting the Inductor

A 1 $\mu$ H to 10 $\mu$ H inductor with a DC current rating at least 25% greater than the maximum load current is recommended for most applications. For higher efficiency, choose an inductor with a lower DC resistance. A larger-value inductor results in less ripple current and a lower output ripple voltage; however, it also has a larger physical size, higher series resistance, and lower saturation current. A good rule for determining the inductance is to allow the inductor ripple current to be approximately 30% of the maximum load current. The inductance (L) can be calculated with Equation(10):

$$L = \frac{V_{OUT}}{f_{SW} \times \Delta I_L} \times \left(1 - \frac{V_{OUT}}{V_{IN}}\right) \quad (10)$$

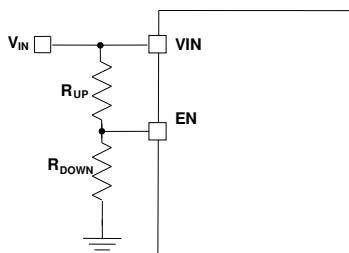
Where  $\Delta I_L$  is the peak-to-peak inductor ripple current.

Choose the inductor ripple current to be approximately 30% of the maximum load current. The maximum peak inductor current ( $I_{LP}$ ) can be calculated with Equation (11):

$$I_{LP} = I_{LOAD} + \frac{V_{OUT}}{2f_{SW} \times L} \times \left(1 - \frac{V_{OUT}}{V_{IN}}\right) \quad (11)$$

### $V_{IN}$ UVLO Setting

The MPQ4436A has an internal, fixed under-voltage lockout (UVLO) threshold. The rising threshold is 3V, while the falling threshold is about 2.7V. For applications that require a higher UVLO point, an external resistor divider between  $V_{IN}$  and EN can be used to achieve a higher equivalent UVLO threshold (see Figure 7).



**Figure 7: Adjustable UVLO Using EN Divider**

The UVLO rising and falling thresholds can be calculated with Equation (12) and Equation (13), respectively:

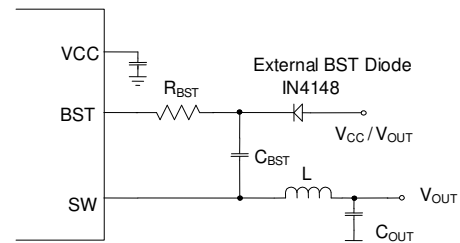
$$V_{IN\_UVLO\_RISING} = \left(1 + \frac{R_{UP}}{R_{DOWN}}\right) \times V_{EN\_RISING} \quad (12)$$

$$V_{IN\_UVLO\_FALLING} = \left(1 + \frac{R_{UP}}{R_{DOWN}}\right) \times V_{EN\_FALLING} \quad (13)$$

Where  $V_{EN\_RISING}$  is 1V, and  $V_{EN\_FALLING}$  is 0.85V.

### External BST Diode and Resistor

An external BST diode can enhance the efficiency of the regulator when the duty cycle is high. A power supply between 2.5V and 5V can be used to power the external BST diode.  $V_{CC}$  or  $V_{OUT}$  is recommended to be this power supply in the circuit (see Figure 8).



**Figure 8: Optional External Bootstrap Diode to Enhance Efficiency**

The recommended external BST diode is IN4148, and the recommended  $C_{BST}$  value is 0.1 $\mu$ F to 1 $\mu$ F. A resistor in series with  $C_{BST}$  ( $R_{BST}$ ) can reduce the SW rising rate and voltage spikes. This enhances EMI performance and reduces voltage stress at a high  $V_{IN}$ . A higher resistance improves SW spike reduction but compromises efficiency. To make a tradeoff between EMI and efficiency, a  $\leq 20\Omega$   $R_{BST}$  is recommended.

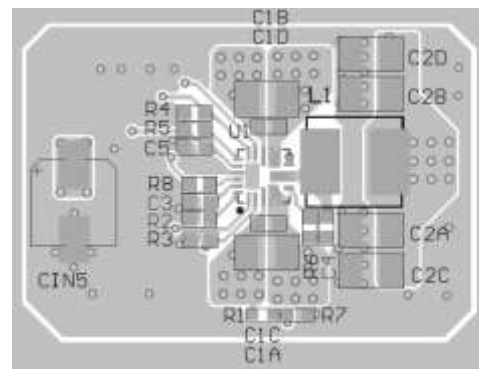
### PCB Layout Guidelines <sup>(8)</sup>

Efficient PCB layout, especially input capacitor placement, is critical for stable operation. A 4-layer layout is strongly recommended to achieve better thermal performance. For best results, refer to Figure 9 and follow the guidelines below:

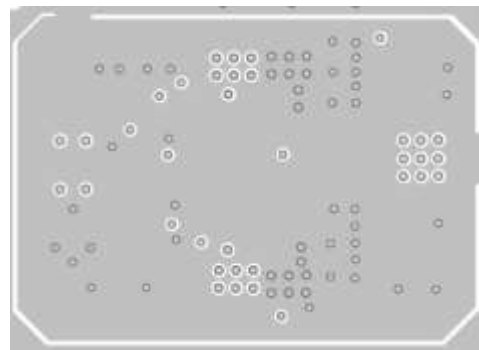
1. Place symmetric input capacitors as close to VIN and GND as possible.
2. Connect a large ground plane directly to PGND.
3. If the bottom layer is a ground plane, add vias near PGND.
4. Ensure that the high-current paths at GND and VIN have short, direct, and wide traces.
5. Place the ceramic input capacitor, especially the small package size (0603) input bypass capacitor, as close to VIN and PGND as possible to minimize high-frequency noise.
6. Keep the connection between the input capacitor and VIN as short and wide as possible.
7. Place the VCC capacitor as close to VCC and GND as possible.
8. Route SW and BST away from sensitive analog areas, such as FB.
9. Place the feedback resistors close to the chip to ensure the trace that connects to FB is as short as possible.
10. Use multiple vias to connect the power planes to the internal layers.

**Note:**

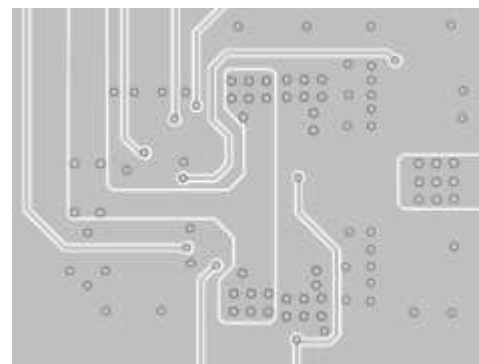
- 8) The recommended PCB layout is based on Figure 10 on page 35.



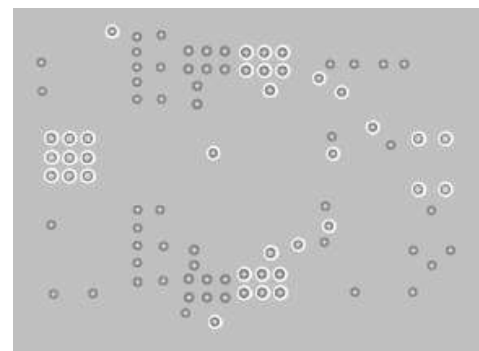
**Top Layer**



**Mid-Layer 1**

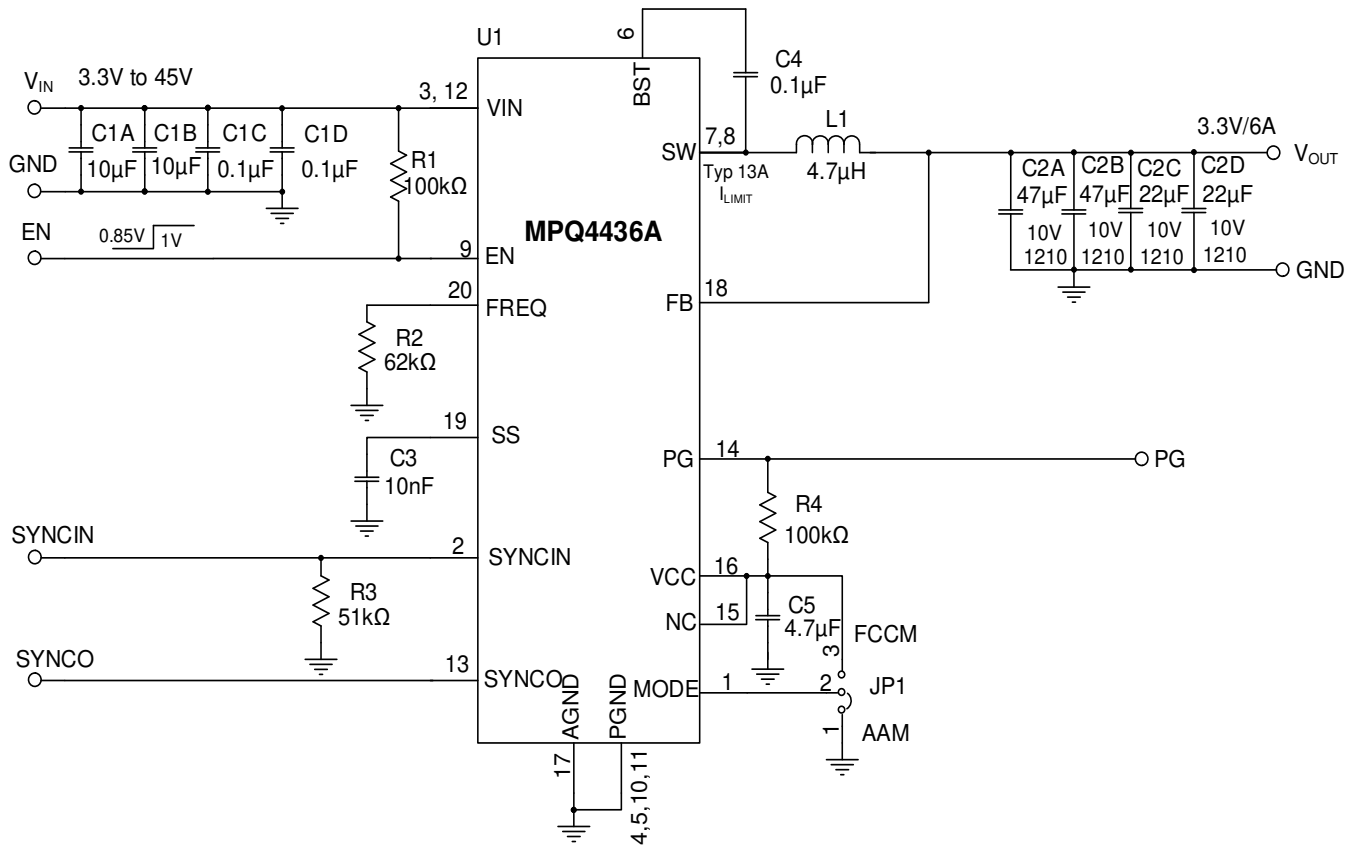


**Mid-Layer 2**



**Bottom Layer**

**Figure 9: Recommended PCB Layout**

**TYPICAL APPLICATION CIRCUITS**

**Figure 10:  $V_{OUT} = 3.3V$ ,  $f_{sw} = 470kHz$**

TYPICAL APPLICATION CIRCUITS (continued)

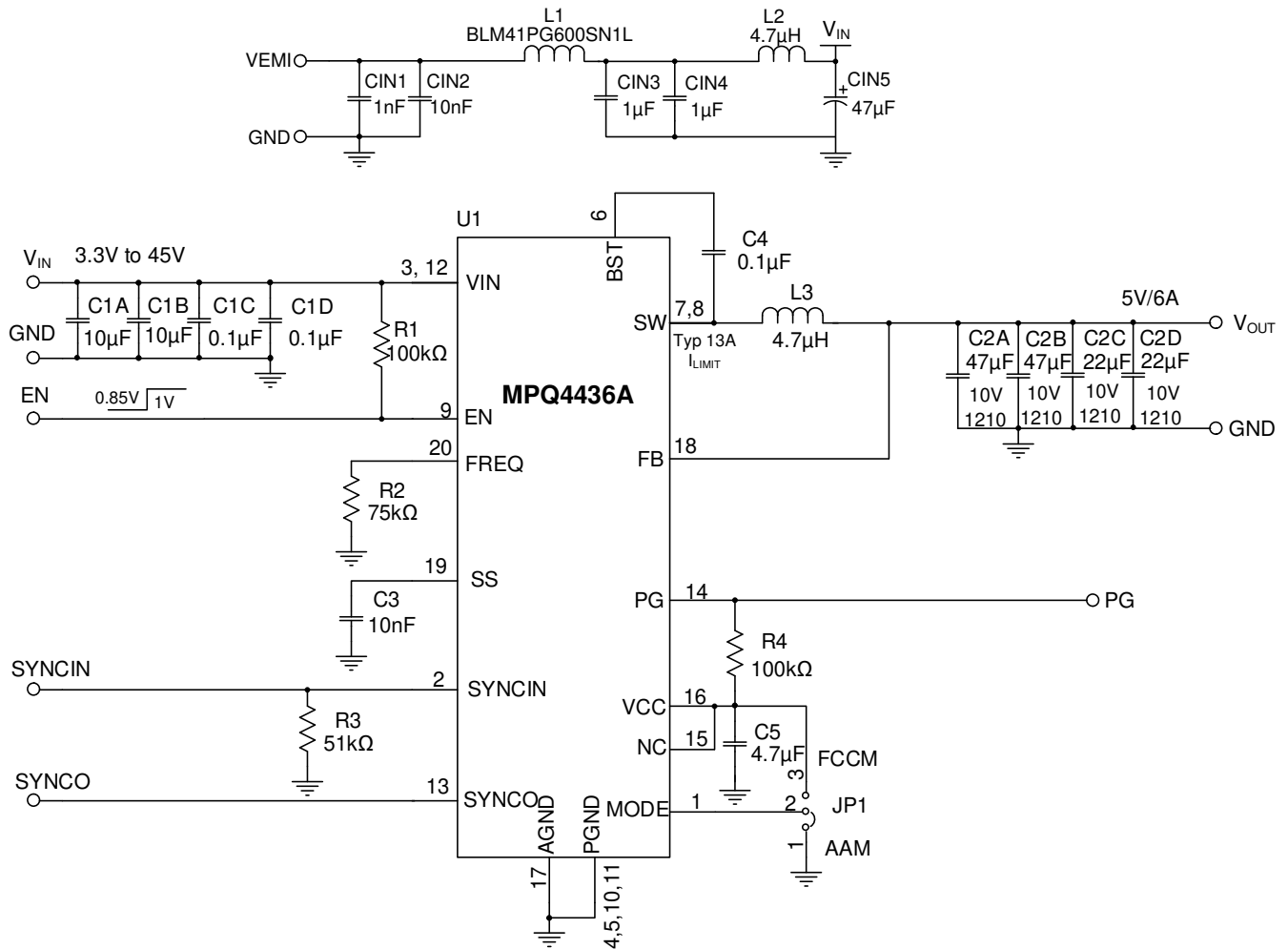
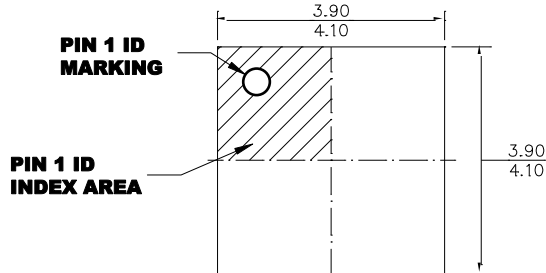


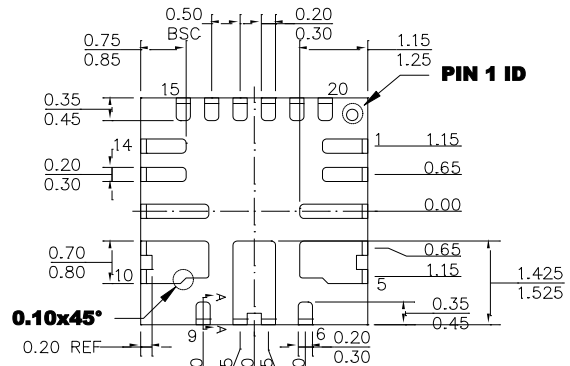
Figure 11:  $V_{out} = 5V$ ,  $f_{sw} = 410kHz$  with EMI Filters

## PACKAGE INFORMATION

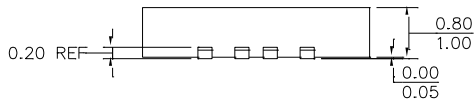
### QFN-20 (4mmx4mm) Wettable Flank



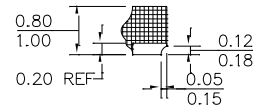
**TOP VIEW**



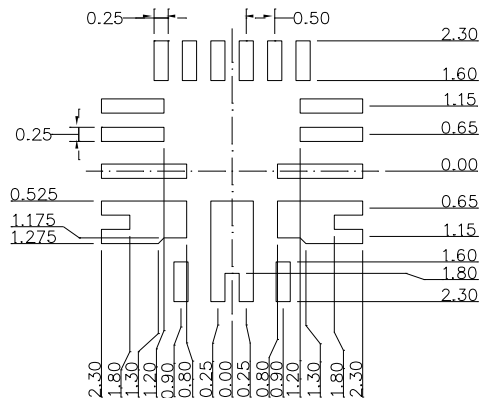
**BOTTOM VIEW**



**SIDE VIEW**



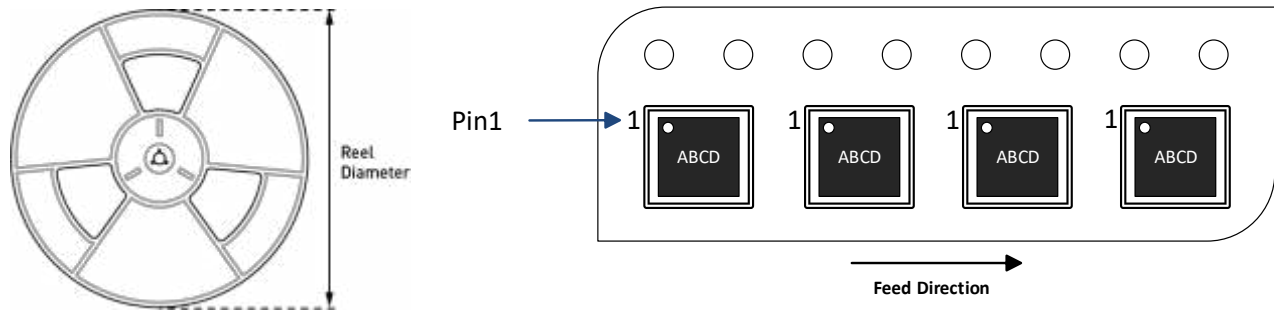
**SECTION A-A**



**RECOMMENDED LAND PATTERN**

**NOTE:**

- 1) THE LEAD SIDE IS WETTABLE.
- 2) ALL DIMENSIONS ARE IN MILLIMETERS.
- 3) LEAD COPLANARITY SHALL BE 0.08 MILLIMETERS MAX.
- 4) JEDEC REFERENCE IS MO-220.
- 5) DRAWING IS NOT TO SCALE.

**CARRIER INFORMATION**


Part Number	Package Description	Quantity/ Reel	Quantity/ Tube	Quantity/ Tray	Reel Diameter	Carrier Tape Width	Carrier Tape Pitch
MPQ4436AGRE-33-AEC1-Z	QFN-20 (4mmx4mm)	5000	N/A	N/A	13in	12mm	8mm
MPQ4436AGRE-5-AEC1-Z	QFN-20 (4mmx4mm)	5000	N/A	N/A	13in	12mm	8mm



## REVISION HISTORY

Revision #	Revision Date	Description	Pages Updated
1.0	1/26/2022	Initial Release	-

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